

Functional Safety PMIC with Built-In WDT Function for Automotive Radar Modules

1 General Description

The RTQ2081-QF is a highly integrated PMIC designed for automotive camera applications. It includes three step-down converters, one high PSRR low-dropout (LDO) regulator, and one general low-dropout (LDO) regulator.

The high-voltage step-down converter operates with an input voltage range of up to 24V and is capable of sustaining a 36V load dump. It is suitable for a direct connection to a 12V battery.

The RTQ2081-QF offers overvoltage and undervoltage monitors, two error input receivers, one error output indicator, and fault status reported by I²C for functional safety purposes.

The RTQ2081-QF is equipped with a standard built-in watchdog timer function. This feature offers versatility for a wide range of applications through configurable setting for both upper and lower window tolerances.

The device offers system design flexibility with I²C or factory-trimmed configurable functions, including adjustable output voltage for each channel, customizable power-on sequencing, overvoltage (OV) or undervoltage (UV) monitor threshold voltage, and the watchdog timeout setting. The RTQ2081-QF is available in a WET-WQFN-24AL 4x4 package with wettable flanks.

The recommended junction temperature range is -40°C to 125°C, and the ambient temperature range is -40°C to 125°C.

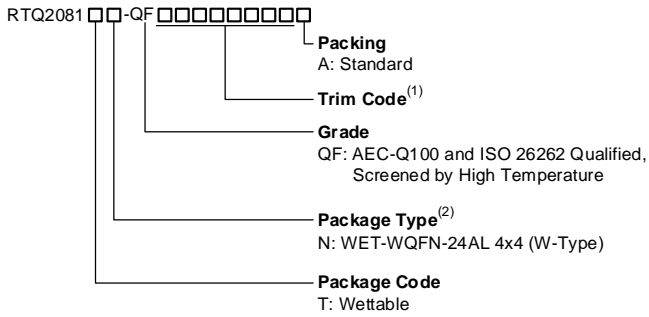
2 Applications

- Functional Safety Related Automotive Modules
 - ADAS MCU
 - Radar Modules
 - Front Radars
 - Rear Radars
 - Side Radars
 - Corner Radars
 - In-Cabin Radars

3 Features

- AEC-Q100 Grade 1 Qualified
- Compliance with ISO 26262 ASIL B
- Safety Mechanisms Include Power-On Built-In Self-Test (BIST) for OV/UV Monitors, I²C Cyclic Redundancy Check (CRC), and OTP Register CRC
- Three Step-Down Converters (HVBuck1, LVBuck2 & 3) with Peak-Current Control, Forced PWM (FPWM), and Power-Saving (PSM) Operation to Enhance Efficiency under Light Load Conditions
 - Fixed Switching Frequency at 2.1MHz
 - EMI Reduction Features including Spread Spectrum and Phase-Shift Operation
 - HVBuck1 Supports Input Voltage from 4V to 24V with 36V Load Dump Protection, Adjustable Output Voltage, and up to 1.5A Output Current
 - LVBuck2 and LVBuck3 Support Input Voltage from 2.7V to 5V, Adjustable Output Voltage, and up to 1.5A Output Current
 - Pins Related to LVBuck2/LVBuck3 Can Float if the Channel is Unused
- Two Low Dropout Regulators (LDO1 and LDO2)
 - LDO1 with 2.7V to 5V Input Voltage, Adjustable Output Voltage, up to 0.3A Output Current, and High PSRR with 0.1A Output Current (60dB at 100kHz, 40dB at 1MHz)
 - LDO2 with 2.7V to 5V Input Voltage, Adjustable Output Voltage, and up to 0.4A Output Current
- Input and Output Functions
 - Monitoring WDT Input Signal from External MCU via WDI
 - WDT Error Status Indication via WDERR
 - RESET Input Signal Control via RESETIN
 - Power Status Indication via PGOOD
 - Error Status Indication via ERROUT
- Small Form Factor
 - Wettable WET-WQFN-24AL 4x4 Package with Compact BOM
- Junction Temperature Range: -40°C to 125°C
- Ambient Temperature Range: -40°C to 125°C

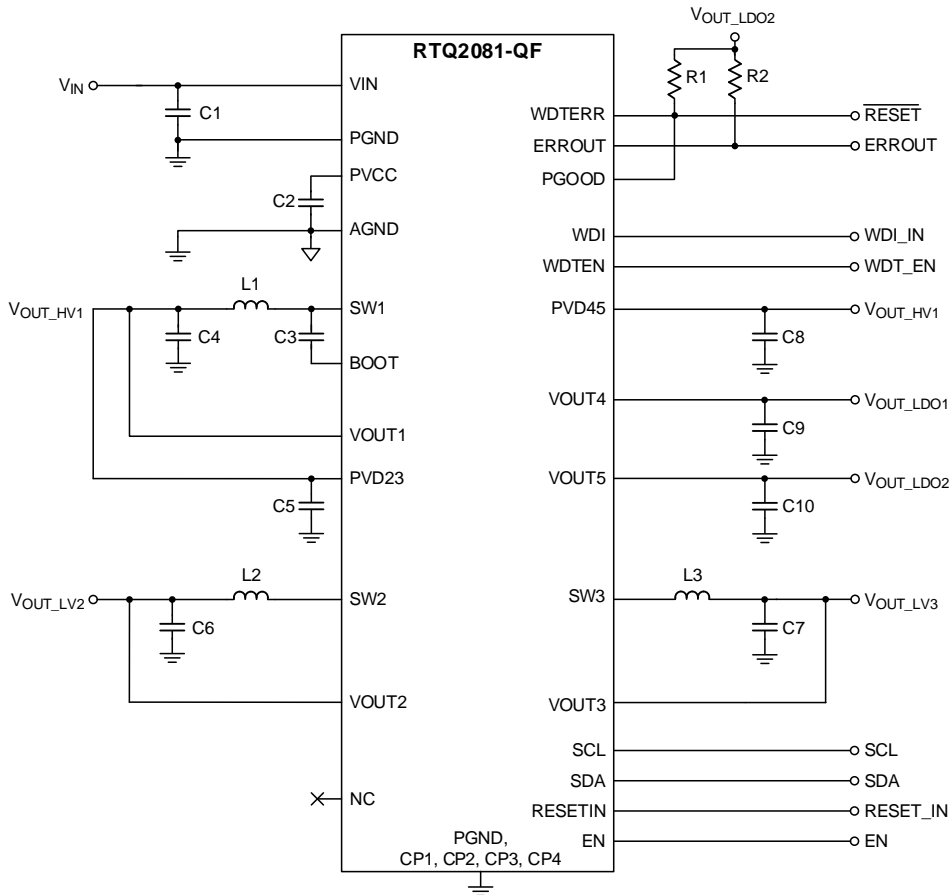
4 Ordering Information



Note 1.

- Marked with ⁽¹⁾ indicated: The trim code for UVLO + REBOOT, POWER_ON_SEQ + SSP, ON_Td + UV HVCH, OFF_Td, HVBUCK1 VOUT, LVBUCK2 VOUT, LVBUCK3 VOUT, LDO1 VOUT, and LDO2 VOUT settings has various combinations. For more details, contact our sales representative directly or through a Richtek distributor in your area.
- Richtek products are Richtek Green Policy compliant and marked with ⁽²⁾ indicates compatible with the current requirements of IPC/JEDEC J-STD-020.

6 Simplified Application Circuit



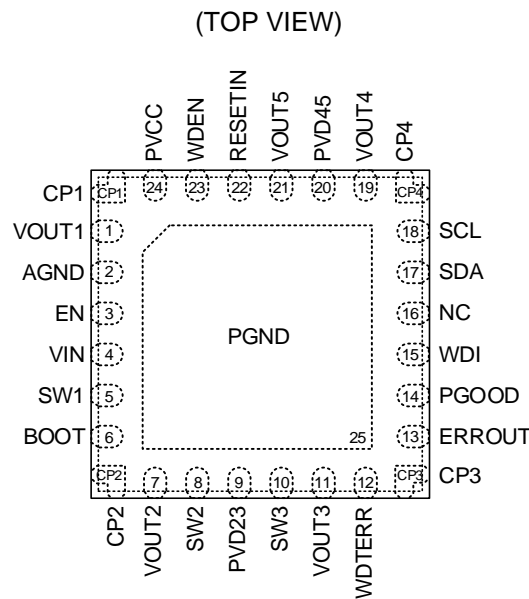
5 Marking Information

For marking information, contact our sales representative directly or through a Richtek distributor located in your area.

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7 Pin Configuration



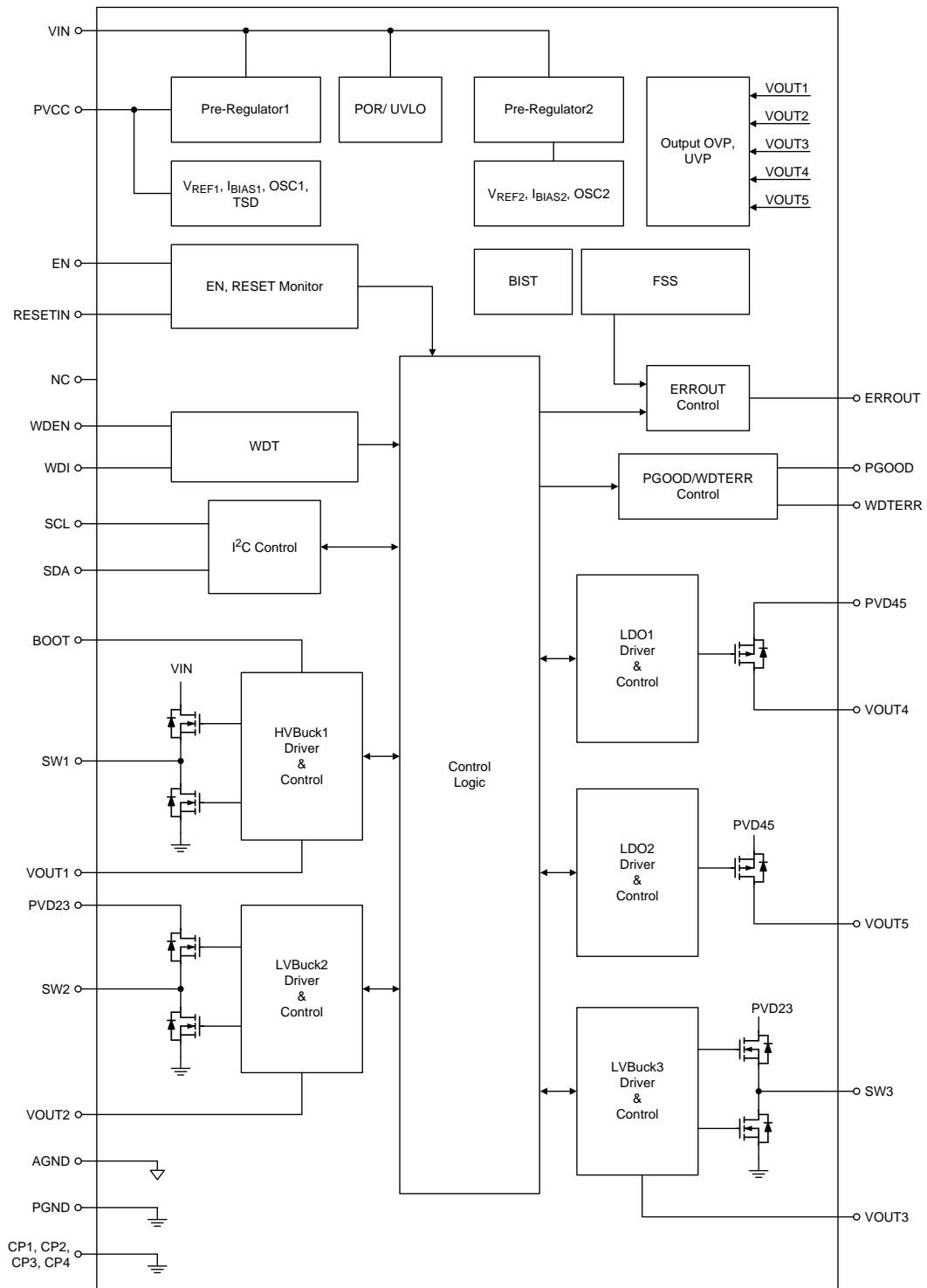
WET-WQFN-24AL 4x4

8 Functional Pin Description

Pin No.	Pin Name	Pin Function
1	VOUT1	HVBuck1 output voltage feedback. It is recommended to directly connect the output capacitor node to this pin for better regulation.
2	AGND	Analog ground for the PMIC analog circuit.
3	EN	Chip hardware enable input pin. When the EN = High, the I ² C read/write function is enabled.
4	VIN	HVBuck1 and PMIC system input power source.
5	SW1	HVBuck1 switch node.
6	BOOT	HVBuck1 BOOT pin.
7	VOUT2	LVBuck2 output voltage feedback. It is recommended to directly connect the output capacitor node to this pin for better regulation.
8	SW2	LVBuck2 switch node.
9	PVD23	LVBuck2/3 input power source. Assume that PVD23 connects to the HVbuck1 output.
10	SW3	LVBuck3 switch node.
11	VOUT3	LVBuck3 output voltage feedback. It is recommended to directly connect the output capacitor node to this pin for better regulation.
12	WDTERR	Open-drain watchdog error indication. If a WDT fault is detected and the WDT_FAULT bit is 0, the WDTERR pin will momentarily go low for 200μs to signal the system of the fault.
13	ERROUT	Open-drain output. ERROUT changes the output status until the PMIC detects faults for indication.
14	PGOOD	Open-drain output, PMIC power status for indication. When PGOOD is in a high state, it indicates all outputs are functioning normally.

Pin No.	Pin Name	Pin Function
15	WDI	Watchdog input signal pin. The input signal is sent by the external system.
16	NC	No internal connection. It is suggested to connect to GND directly.
17	SDA	I ² C interface serial data pin, open-drain. Connect to an external pull-up resistor is required.
18	SCL	I ² C interface serial clock input pin, open-drain. Connect to an external pull-up resistor is required.
19	VOUT4	LDO1 output pin. It is recommended to directly connect the output capacitor node to this pin for better regulation.
20	PVD45	LDO1/2 input power source. Assume that PVD45 connects to the HVbuck1 output.
21	VOUT5	LDO2 output pin. It is recommended to directly connect the output capacitor node to this pin for better regulation.
22	RESETIN	Chip external reset input pin activated by a high signal.
23	WDEN	WDT default ON/OFF setting pin. It is suggested to connect PVCC to the WDEN pin by a 10kΩ resistor when WDT function needs to be default ON.
24	PVCC	Internal analog power output. Connect a 1μF ceramic decoupling capacitor between this pin and ground. Additional external loading to this pin is forbidden.
25 (Exposed Pad)	PGND	IC thermal pad and power ground. It must be connected to the main ground plane for proper operation.
CP1	CP1	Corner Pins for package reliability improvement. These pins are internally connected to the Exposed Pad.
CP2	CP2	
CP3	CP3	
CP4	CP4	

9 Functional Block Diagram



10 Absolute Maximum Ratings

(Note 2)

- VIN, EN, SW1 ----- -0.3V to 36V
- BOOT ----- -0.3V to 36V
- BOOT to SW1 ----- -0.3V to 5V
- VOUT1, VOUT2, SW2, PVD23, SW3, VOUT3, WDTERR, ERRROUT, PGOOD,
WDI, SDA, SCL, VOUT4, PVD45, VOUT5, RESETIN, WDEN, PVCC ----- -0.3V to 6.5V
- Lead Temperature (Soldering, 10 sec.)----- 260°C
- Junction Temperature----- 150°C
- Storage Temperature Range----- -65°C to 150°C

Note 2. Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

11 ESD Susceptibility

(Note 3)

- ESD Susceptibility
HBM (Human Body Model) ----- 2kV

Note 3. Devices are ESD sensitive. Handling precautions are recommended.

12 Recommended Operating Conditions

(Note 4)

- Supply Voltage, VIN ----- 4V to 24V
- Supply Voltage, VPVD23, VPVD45 ----- 2.7V to 5V
- Ambient Temperature Range ----- -40°C to 125°C
- Junction Temperature Range ----- -40°C to 125°C

Note 4. The device is not guaranteed to function outside its operating conditions.

13 Thermal Information

(Note 5)

Thermal Parameter		WET-WQFN-24AL 4x4	Unit
θJA	Junction-to-ambient thermal resistance (JEDEC standard)	37	°C/W
θJC(Top)	Junction-to-case (top) thermal resistance	34.8	°C/W
θJC(Bottom)	Junction-to-case (bottom) thermal resistance	0.48	°C/W
θJB	Junction-to-board thermal resistance	9.72	°C/W

Note 5. For more information about thermal parameter, see the Application and Definition of Thermal Resistances report, [AN061](#).

14 Electrical Characteristics

($T_A = T_J = -40^{\circ}\text{C}$ to 125°C , $V_{IN} = 6\text{V}$, $V_{OUT_HV1} = 3.6\text{V}$, $V_{OUT_LV2} = 1.1\text{V}$, $V_{OUT_LV3} = 1.8\text{V}$, $V_{OUT_LDO1} = 3.3\text{V}$, $V_{OUT_LDO2} = 1.8\text{V}$, unless otherwise specified.)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
System						
Shutdown Current of VIN	ISHUTDOWN	EN = L, $V_{IN} \leq 12\text{V}$, V_{OUT_HV1} tied to PVD23 and PVD45	0	--	20	μA
VIN Undervoltage Lockout Falling	VUVLO_F	TOP_CFG [4:3] = 2'b00	3.135	3.3	3.465	V
VIN Undervoltage Lockout Rising	VUVLO_R	TOP_CFG [4:3] = 2'b00	3.61	3.8	3.99	V
VIN Overvoltage Rising Threshold	VOVP_R_VIN		24.735	25.5	26.265	V
VIN Overvoltage Hysteresis	VOVP_HYS_VIN		5	6	7	V
Pre-Regulator (Note 6)						
PVCC Voltage Range	VPVCC		4.26	4.58	4.92	V
CH1_HVBuck1						
Input Voltage Range	VIN_HV1	$V_{IN_HV1} = V_{IN}$	4	--	24	V
Output Voltage Range	VOUT_HV1	$V_{IN_HV1} = 4\text{V}$ to 24V	2.7	--	5	V
Output Voltage Accuracy	VOUT_ACC_HV1_FPWM	$V_{OUT_HV1} = 2.7\text{V}$ to 5V , $V_{IN_HV1} = 6\text{V}$, 9V , 12V , $I_{OUT_HV1} = 0$ to 1.5A , FPWM	-1.5	--	1.5	%
Soft-Start Time	tSS_HV1	Time for V_{OUT_HV1} to rise from 10% to 90% of the target value, no load	500	1000	1500	μs
Switching Frequency	fSW_HV1		1.89	2.1	2.31	MHz
Spread Spectrum Range	fSSP		--	6	--	%
High-Side MOSFET On-Resistance	RON_UG_HV1		--	220	--	$\text{m}\Omega$
Low-Side MOSFET On-Resistance	RON_LG_HV1		--	120	--	$\text{m}\Omega$
Minimum On-Time	tMIN_ON_HV1		--	--	40	ns
Minimum Off-Time	tMIN_OFF_HV1		--	--	50	ns
Positive Inductor Peak Current Limit	ICL_PK_HV1		1.9	2.5	3.1	A

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Positive Inductor Valley Current Limit	ICL_VALLEY_HV1		--	1.6	--	A
Negative Inductor Peak Current Limit	ICL_N_PK_HV1	HVBuck1 in FPWM	1.3	1.8	2.3	A
Output Discharge Resistor	RDIS_HV1		20	47	80	Ω
HVBuck1 Output Undervoltage Falling Threshold Detection	VUVP_HV1		--	80	--	%
HVBuck1 Output Undervoltage Falling Threshold Detection Accuracy	VUVP_ACC_HV1		-1.3	--	1.3	%
HVBuck1 Output Overvoltage Rising Threshold Detection	VOVP_HV1		--	110	--	%
HVBuck1 Output Overvoltage Rising Threshold Detection Accuracy	VOVP_ACC_HV1		-1.3	--	1.3	%
CH2_LVBuck2						
Input Voltage Range	VIN_LV2		2.7	--	5	V
Output Voltage Range	VOUT_LV2		0.6	1.1	1.9	V
Output Voltage Accuracy	VOUT_ACC_LV2_FPWM	VOUT_LV2 = 0.6V to 1.9V, VIN_LV2 = 3.6V, IOUT_LV2 = 0A to 1.5A, FPWM	-1.5	--	1.5	%
Soft-Start Time	tSS_LV2	Time for VOUT_LV2 to rise from 10% to 90% of the target value, no load	600	1200	1800	μs
Switching Frequency	fSW_LV2		1.89	2.1	2.31	MHz
Spread-Spectrum Range	fSSP		--	6	--	%
High-Side MOSFET On-Resistance	RON_UG_LV2		--	90	--	mΩ
Low-Side MOSFET On-Resistance	RON_LG_LV2		--	35	--	mΩ

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Minimum On-Time	t _{MIN_ON_LV2}		--	--	44	ns
Positive Inductor Peak Current Limit	I _{CL_PK_LV2}		2.1	2.5	2.9	A
Positive Inductor Valley Current Limit	I _{CL_VALLEY_LV2}		--	1.8	--	A
Negative Inductor Peak Current Limit	I _{CL_N_PK_LV2}	LVBuck2 in FPWM	0.7	1.7	2.9	A
Output Discharge Resistor	R _{DIS_LV2}		6	9	14	Ω
LVBuck2 Output Undervoltage Falling Threshold Detection	V _{UVP_LV2}		--	95	--	%
LVBuck2 Output Undervoltage Falling Threshold Detection Accuracy	V _{UVP_ACC_LV2}		-1.3	--	1.3	%
LVBuck2 Output Overvoltage Rising Threshold Detection	V _{OV_P_LV2}		--	105	--	%
LVBuck2 Output Overvoltage Rising Threshold Detection Accuracy	V _{OV_P_ACC_LV2}		-1.3	--	1.3	%
PVD23 Overvoltage Rising Protection	V _{OV_P_PVD23}		5.35	5.8	6.25	V
PVD23 Overvoltage Hysteresis	V _{OV_P_HYS_PVD23}		--	580	--	mV
CH3_LVBuck3						
Input Voltage Range	V _{IN_LV3}		2.7	--	5	V
Output Voltage Range	V _{OUT_LV3}		0.6	--	1.9	V
Output Voltage Accuracy	V _{OUT_ACC_LV3_FPWM}	V _{OUT_LV3} = 0.6V to 1.9V, V _{IN_LV3} = 3.6V, I _{OUT_LV3} = 0A to 1.5A, FPWM	-1.5	--	1.5	%
Soft-Start Time	t _{SS_LV3}	Time for V _{OUT_LV3} to rise from 10% to 90% of the target value, no load	600	1200	1800	μs

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Switching Frequency	f _{SW_LV3}		1.89	2.1	2.31	MHz
Spread-Spectrum Range	f _{SSP}		--	6	--	%
High-Side MOSFET On-Resistance	R _{ON_UG_LV3}		--	90	--	mΩ
Low-Side MOSFET On-Resistance	R _{ON_LG_LV3}		--	42	--	mΩ
Minimum On-Time	t _{MIN_ON_LV3}		--	--	44	ns
Positive Inductor Peak Current Limit	I _{CL_PK_LV3}		2.1	2.5	2.9	A
Positive Inductor Valley Current Limit	I _{CL_VALLEY_LV3}		--	1.8	--	A
Negative Inductor Peak Current Limit	I _{CL_N_PK_LV3}	LVBuck3 in FPWM	0.7	1.7	2.9	A
Output Discharge Resistor	R _{DIS_LV3}		6	9	14	Ω
LVBuck3 Output Undervoltage Falling Threshold Detection	V _{UVP_LV3}		--	95	--	%
LVBuck3 Output Undervoltage Falling Threshold Detection Accuracy	V _{UVP_ACC_LV3}		-1.3	--	1.3	%
LVBuck3 Output Overvoltage Rising Threshold Detection	V _{OVP_LV3}		--	105	--	%
LVBuck3 Output Overvoltage Rising Threshold Detection Accuracy	V _{OVP_ACC_LV3}		-1.3	--	1.3	%
PVD23 Overvoltage Rising Protection	V _{OVP_PVD23}		5.35	5.8	6.25	V
PVD23 Overvoltage Hysteresis	V _{OVP_HYS_PVD23}		--	580	--	mV

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
CH4_LDO1						
Input Voltage Range	V _{IN_LDO1}		2.7	--	5	V
Output Voltage Range	V _{OUT_LDO1}		1.8	--	3.5	V
Output Voltage Accuracy	V _{OUT_ACC_LDO1}	V _{OUT_LDO1} = 1.8V to 3.5V, (V _{IN_LDO1} - V _{OUT_LDO1}) ≥ 0.3V, I _{OUT_LDO1} = 0mA to 300mA	-1.5	--	1.5	%
Soft-Start Time	t _{SS_LDO1}	Time for V _{OUT_LDO1} to rise from 10% to 90% of the target value, no load	200	700	1100	μs
Dropout Voltage (Note 7)	V _{DROP_300_LDO1}	I _{OUT_LDO1} = 300mA	--	--	300	mV
	V _{DROP_150_LDO1}	I _{OUT_LDO1} = 150mA	--	--	150	
Maximum Output Current	I _{OUT_MAX_LDO1}		300	--	--	mA
Output Current Limit	I _{CL_LDO1}		345	450	555	mA
Output Discharge Resistor	R _{DIS_LDO1}		32	60	88	Ω
LDO1 Output Undervoltage Falling Threshold Detection	V _{UVP_LDO1}		--	95	--	%
LDO1 Output Undervoltage Falling Threshold Detection Accuracy	V _{UVP_ACC_LDO1}		-1.3	--	1.3	%
LDO1 Output Overvoltage Rising Threshold Detection	V _{OV_P_LDO1}		--	105	--	%
LDO1 Output Overvoltage Rising Threshold Detection Accuracy	V _{OV_P_ACC_LDO1}		-1.3	--	1.3	%
PVD45 Overvoltage Rising Protection	V _{OV_P_PVD45}		5.35	5.8	6.25	V
PVD45 Overvoltage Hysteresis	V _{OV_P_HYS_PVD45}		--	500	--	mV

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
CH5_LDO2						
Input Voltage Range	V _{IN_LDO2}		2.7	--	5	V
Output Voltage Range	V _{OUT_LDO2}		1.8	--	3.3	V
Output Voltage Accuracy	V _{OUT_ACC_LDO2}	V _{OUT_LDO2} = 1.8V to 3.5V, (V _{IN_LDO2} - V _{OUT_LDO2}) ≥ 0.4V, I _{OUT_LDO2} = 0mA to 400mA	-1.5	--	1.5	%
Soft-Start Time	t _{SS_LDO2}	Time for V _{OUT_LDO2} to rise from 10% to 90% of the target value, no load	344	410	487	μs
Dropout Voltage (Note 7)	V _{DROP_400_LDO2}	I _{OUT_LDO2} = 400mA	--	--	400	mV
	V _{DROP_150_LDO2}	I _{OUT_LDO2} = 150mA	--	--	150	
Maximum Output Current	I _{OUT_MAX_LDO2}		400	--	--	mA
Output Current Limit	I _{CL_LDO2}		450	600	750	mA
Output Discharge Resistor	R _{DIS_LDO2}		32	60	88	Ω
LDO2 Output Undervoltage Falling Threshold Detection	V _{UVP_LDO2}		--	95	--	%
LDO2 Output Undervoltage Falling Threshold Detection Accuracy	V _{UVP_ACC_LDO2}		-1.3	--	1.3	%
LDO2 Output Overvoltage Rising Threshold Detection	V _{OV_P_LDO2}		--	105	--	%
LDO2 Output Overvoltage Rising Threshold Detection Accuracy	V _{OV_P_ACC_LDO2}		-1.3	--	1.3	%
PVD45 Overvoltage Rising Protection	V _{OV_P_PVD45}		5.35	5.8	6.25	V
PVD45 Overvoltage Hysteresis	V _{OV_P_HYS_PVD45}		--	500	--	mV
I/O Control						
PGOOD Low-Level Output Voltage	V _{OL_PGOOD}	The current into the PGOOD pin is equal to 5mA	--	--	200	mV

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
PGOOD Input Leakage Current	I _{LEAK_PGOOD}	1.8V applied on the PGOOD pin	--	--	1	μA
PGOOD Delay Time	t _{PGOOD_DLY}	Time interval between the completion of the soft-start process for the last channel and the subsequent assertion of the PGOOD signal	8.3	9.4	10.5	ms
EN Low-Level Input Voltage	V _{IL_EN}		--	--	0.4	V
EN High-Level Input Voltage	V _{IH_EN}		1.2	--	--	V
EN Pull-Down Current	I _{PD_EN}		1	--	11	μA
RESETIN Low-Level Input Voltage	V _{IL_RESETIN}		--	--	0.4	V
RESETIN High-Level Input Voltage	V _{IH_RESETIN}		1.2	--	--	V
RESETIN Pull-Down Resistance	R _{PD_RESETIN}		--	300	--	kΩ
Safety I/O Control						
ERROUT Low-Level Output Voltage	V _{OL_ERROUT}	The current into ERROUT is equal to 5mA	--	--	200	mV
ERROUT Input Leakage Current	I _{LEAK_ERROUT}	1.8V applied on the ERROUT pin	--	--	1	μA
WDT Control						
WDEN High-Voltage Level	V _{WDEN_H}		1.4	--	--	V
WDEN Low-Voltage Level	V _{WDEN_L}		--	--	0.4	V
WDI High-Level Input Voltage	V _{IH_WDI}		1.2	--	--	V
WDI Low-Level Input Voltage	V _{IL_WDI}		--	--	0.4	V
WDI Pull-Down Resistance	R _{PD_WDI}		--	300	--	kΩ
WDTERR Low-Level Output Voltage	V _{OL_WDTERR}	The current into the WDTERR pin is equal to 5mA	--	--	200	mV
WDTERR Input Leakage Current	I _{LEAK_WDTERR}	1.8V applied on WDTERR pin	--	--	1	μA

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
WDT Timeout Lower Limit	tWDT_LOWER	If the host kicks the input command too early and below the lower limit, it can be regarded as a WDT too-fast fault.	25.05	27	30.8	ms
			30.42	33	36.96	
			121.68	133	147.83	
WDT Timeout Upper Limit	tWDT_UPPER	If the host kicks the input command too slowly and exceeds the upper limit, it can be regarded as a WDT too-slow fault.	50.1	54	59.54	ms
			60.84	66	73.91	
			221.89	239	262.8	
WDTERR Toggle Time	tWDTERR	When a WDT fault is triggered, the WDTERR pin goes low for 200 μ s before returning high (WDT_FAULT bit = 0).	--	200	--	μ s

Note 6. PVCC is the pre-regulator output voltage only for internal circuitry. External loading on the PVCC pin is forbidden.

Note 7. Dropout voltage is the voltage difference between the input and the output at which the output voltage drops to 100mV below its nominal value.

14.1 System Characteristics

The following specifications are guaranteed by design and are not performed in production testing. ($T_A = T_J = -40^{\circ}\text{C}$ to 125°C , $V_{IN} = 6\text{V}$, $V_{OUT_HV1} = 3.6\text{V}$, $V_{OUT_LV2} = 1.1\text{V}$, $V_{OUT_LV3} = 1.8\text{V}$, $V_{OUT_LDO1} = 3.3\text{V}$, $V_{OUT_LDO2} = 1.8\text{V}$, unless otherwise specified.)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
System						
Quiescent Current of VIN	I _{Q_ON}	EN = H, $V_{UVLO_R} \leq V_{IN} \leq 24\text{V}$, V_{OUT_HV1} ties to PVD23 and PVD45, all channels are ON, no load	--	20	--	mA
Quiescent Current of VIN	I _{Q_OFF}	EN = H, $V_{UVLO_R} \leq V_{IN} \leq 24\text{V}$, V_{OUT_HV1} ties to PVD23 and PVD45, all channels are OFF	--	3	--	mA
Over-Temperature Protection	T _{TSD}		--	170	--	$^{\circ}\text{C}$
Over-Temperature Protection Hysteresis	T _{TSD_H}		--	20	--	$^{\circ}\text{C}$
Over-Temperature Warning	T _{TOTW}		--	130	--	$^{\circ}\text{C}$
Over-Temperature Warning Hysteresis	T _{TOTW_H}		--	20	--	$^{\circ}\text{C}$

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
CH1_HVBuck1						
Maximum Output Current	IOUT_MAX_HV1	Depends on the input voltage and the output voltage	1.5	--	--	A
Load Transient	VLOAD_TRAN_HV1_FPWM	VOUT_HV1 = 3.6V, VIN_HV1 = 6V/9V/12V, IOUT_HV1 = 10mA to 0.5A to 10mA, 1μs, FPWM	-150	--	150	mV
Line Transient	VLINE_TRAN_HV1_FPWM	VOUT_HV1 = 3.6V, VIN_HV1 = 5V to 18.5V to 5V, 100μs, IOUT_HV1 = 0.5A, FPWM	-50	--	50	mV
Load Regulation	VLOAD_REG_HV1	VOUT_HV1 = 3.6V, VIN_HV1 = 6V/9V/12V, ΔIOUT_HV1 = 1.5A, FPWM	--	--	0.15	%
Line Regulation	VLINE_REG_HV1	VOUT_HV1 = 3.6V, VIN_HV1 = 5V to 18.5V, IOUT_HV1 = 1.5A	--	--	1	%
Output Ripple Voltage	VRIPPLE_HV1_FPWM	Peak to peak in one switching cycle, FPWM, SSP_EN bit = 0	--	--	20	mVpp
CH2_LVBuck2						
Maximum Output Current	IOUT_MAX_LV2		1.5	--	--	A
Load Transient	VLOAD_TRAN_LV2_FPWM	VOUT_LV2 = 1.1V, VIN_LV2 = 3.6V, IOUT_LV2 = 100mA to 0.5A to 100mA, 1μs, FPWM	-50	--	50	mV
Line Transient	VLINE_TRAN_LV2_FPWM	VOUT_LV2 = 1.1V, VIN_LV2 = 3V to 5V to 3V, 50μs, IOUT_LV2 = 10mA/0.75A/1.5A, FPWM	-50	--	50	mV
Load Regulation	VLOAD_REG_LV2	VOUT_LV2 = 1.1V, VIN_LV2 = 3.6V, ΔIOUT_LV2 = 1.5A, FPWM	--	--	0.15	%
Line Regulation	VLINE_REG_LV2	VOUT_LV2 = 1.1V, VIN_LV2 = 2.7V to 5V, IOUT_LV2 = 1.5A	--	--	1	%
Output Ripple Voltage	VRIPPLE_LV2_FPWM	Peak to peak in one switching cycle, FPWM, SSP_EN bit = 0	--	10	15	mVpp
CH3_LVBuck3						
Maximum Output Current	IOUT_MAX_LV3		1.5	--	--	A
Load Transient	VLOAD_TRAN_LV3_FPWM	VOUT_LV3 = 1.8V, VIN_LV3 = 3.6V, IOUT_LV3 = 100mA to 0.5A to 100mA, 1μs, FPWM	-50	--	50	mV

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Line Transient	V _{LINE_TRAN_LV3_FPWM}	V _{OUT_LV3} = 1.8V, V _{IN_LV3} = 3V to 5V to 3V, 50μs, I _{OUT_LV3} = 10mA/0.75A/1.5A, FPWM	-50	--	50	mV
Load Regulation	V _{LOAD_REG_LV3}	V _{OUT_LV3} = 1.8V, V _{IN_LV3} = 3.6V, ΔI _{OUT_LV3} = 1.5A, FPWM	--	--	0.15	%
Line Regulation	V _{LINE_REG_LV3}	V _{OUT_LV3} = 1.8V, V _{IN_LV3} = 2.7V to 5V, I _{OUT_LV3} = 1.5A	--	--	1	%
Output Ripple Voltage	V _{RIPPLE_LV3_FPWM}	Peak to peak in one switching cycle, FPWM, SSP_EN bit = 0	--	10	15	mVpp
CH4_LDO1						
Power Supply Rejection Ratio	PSRR _{LDO1}	V _{OUT_LDO1} = 3.3V, V _{IN_LDO1} ≥ 3.6V, I _{OUT_LDO1} = 100mA, f = 100kHz Disturbing signal = 100mV	--	60	--	dB
		V _{OUT_LDO1} = 3.3V, V _{IN_LDO1} ≥ 3.6V, I _{OUT_LDO1} = 100mA, f = 100kHz to 1MHz Disturbing signal = 100mV	--	40	--	
Load Transient	V _{LOAD_TRAN_LDO1}	V _{OUT_LDO1} = 3.3V, V _{IN_LDO1} = 3.6V, I _{OUT_LDO1} = 10mA to 0.2A to 10mA, 1μs, C _{O_LDO1} = 2.2μF	-25	--	25	mV
Line Transient	V _{LINE_TRAN_LDO1}	V _{OUT_LDO1} = 3.3V, V _{IN_LDO1} step 600mV, 10μs, the LDO1 is not in dropout condition, I _{OUT_LDO1} = 1mA/ 0.3A	-25	--	25	mV
CH5_LDO2						
Power Supply Rejection Ratio	PSRR _{LDO2}	V _{OUT_LDO2} = 3.3V, V _{IN_LDO2} ≥ 3.7V, I _{OUT_LDO2} = 100mA, f = 100kHz Disturbing signal = 100mV	--	20	--	dB
		V _{OUT_LDO2} = 3.3V, V _{IN_LDO2} ≥ 3.7V, I _{OUT_LDO2} = 100mA, f = 100kHz to 1MHz Disturbing signal = 100mV	--	15	--	
Load Transient	V _{LOAD_TRAN_LDO2}	V _{OUT_LDO2} = 1.8V, V _{IN_LDO2} = 3.6V, I _{OUT_LDO2} = 10mA to 0.2A to 10mA, 1μs, C _{O_LDO2} = 2.2μF	-50	--	50	mV
Line Transient	V _{LINE_TRAN_LDO2}	V _{OUT_LDO2} = 1.8V, V _{IN_LDO2} step 600mV, 10μs, the LDO2 is not in dropout condition, I _{OUT_LDO2} = 1mA/ 0.4A	-25	--	25	mV

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
I/O Time Deglitch						
EN Rising Deglitch Time	tEN_R_DEG		--	5	--	μs
EN Falling Deglitch Time	tEN_F_DEG		--	50	--	μs
RESETIN Detection Delay Time	tRESETIN_DET_DLY	Delay time starts detecting RESETIN after PGOOD normal state is ready	--	100	--	μs
RSETIN Rising Deglitch Time	tRSETIN_R_DEG		--	50	--	μs
RSETIN Falling Deglitch Time	tRSETIN_F_DEG		--	5	--	μs
WDT Time Deglitch						
WDI Rising Deglitch Time	tWDI_R_DEG	Start detecting WDI after PGOOD normal state is ready	--	50	--	μs
WDI Falling Deglitch Time	tWDI_F_DEG		--	50	--	μs
Protection Time Deglitch						
HVBuck1 Output UVP Deglitch Time	tUVP_DEG_HV1		--	50	--	μs
LVBuck2 Output UVP Deglitch Time	tUVP_DEG_LV2		--	50	--	μs
LVBuck3 Output UVP Deglitch Time	tUVP_DEG_LV3		--	50	--	μs
LDO1 Output UVP Deglitch Time	tUVP_DEG_LDO1		--	50	--	μs
LDO2 Output UVP Deglitch Time	tUVP_DEG_LDO2		--	50	--	μs
HVBuck1 Output OVP Deglitch Time	tOVP_DEG_HV1		--	50	--	μs
LVBuck2 Output OVP Deglitch Time	tOVP_DEG_LV2		--	50	--	μs
LVBuck3 Output OVP Deglitch Time	tOVP_DEG_LV3		--	50	--	μs
LDO1 Output OVP Deglitch Time	tOVP_DEG_LDO1		--	50	--	μs
LDO2 Output OVP Deglitch Time	tOVP_DEG_LDO2		--	50	--	μs

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
PVD23 OVP Rising Deglitch Time	tOVP_R_DEG_PVD23		--	5	--	μs
PVD23 OVP Falling Deglitch Time	tOVP_F_DEG_PVD23		--	5	--	μs
PVD45 OVP Rising Deglitch Time	tOVP_R_DEG_PVD45		--	5	--	μs
PVD45 OVP Falling Deglitch Time	tOVP_F_DEG_PVD45		--	5	--	μs
HVBuck1 OCP Deglitch Time	tOCP_DEG_HV1		--	1	--	ms
LVBuck2 OCP Deglitch Time	tOCP_DEG_LV2		--	1	--	ms
LVBuck3 OCP Deglitch Time	tOCP_DEG_LV3		--	1	--	ms
LDO1 OCP Deglitch Time	tOCP_DEG_LDO1		--	1	--	ms
LDO2 OCP Deglitch Time	tOCP_DEG_LDO2		--	1	--	ms
I²C						
SCL, SDA High-Level Input Threshold Voltage	V _{IH_I2C}		1.2	--	--	V
SCL, SDA Low-Level Input Threshold Voltage	V _{IL_I2C}		--	--	0.4	V
SCL Clock Frequency	f _{SCL}		--	--	1000	kHz
(Repeated) Start Hold Time	t _{HD;STA}	Hold time (repeated) start condition. After this period, the first clock pulse is generated.	0.26	--	--	μs
SCL Clock Low Time	t _{LOW}		0.5	--	--	μs
SCL Clock High Time	t _{HIGH}		0.26	--	--	μs
(Repeated) Start Setup Time	t _{SU;STA}	Set-up time for a repeated START condition	0.26	--	--	μs
SDA Data Hold Time	t _{HD;DAT}		0	--	--	ns
SDA Set-Up Time	t _{SU;DAT}		50	--	--	ns

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
STOP Condition Setup Time	t _{SU;STO}		0.26	--	--	μs
Bus Free Time between Stop and Start Condition	t _{BUF}		0.5	--	--	μs
Rising Time of Both SDA and SCL Signals	t _R		--	--	120	ns
Falling Time of Both SDA and SCL Signals	t _F		--	--	120	ns
SDA Output Low Sink Current	I _{OL_I2C}	SDA voltage = 0.4V	2	--	--	mA
SDA Valid Acknowledge Time	t _{VD;ACK}		--	--	0.45	μs
Component Constraint						
Effective Output Inductance	LHV1		1	1.5	2	μH
	LLV2		0.68	1	1.2	
	LLV3		0.68	1	1.2	
Effective Boot Capacitance	C _{BOOT}		0.07	0.1	0.13	μF
Effective PVCC Capacitance	C _{PVCC}		0.3	1	1.4	μF
Effective Input Capacitance	C _{IN_VIN}		1.5	4.7	10	μF
	C _{IN_PVD23}		1.5	4.7	10	
	C _{IN_PVD45}		0.7	2.2	4	
Effective Output Capacitance	CO_HV1		3.3	10	14	μF
	CO_LV2		4.5	10	14	
	CO_LV3		4.5	10	14	
	CO_LDO1		0.7	2.2	33	
	CO_LDO2		0.7	2.2	22	
Output Capacitance ESR for HV _{Buck} 1, LV _{Buck} 2, LV _{Buck} 3, LDO1, and LDO2	CO_ESR		--	10	20	mΩ

15 Typical Application Circuit

15.1 General Radar Application

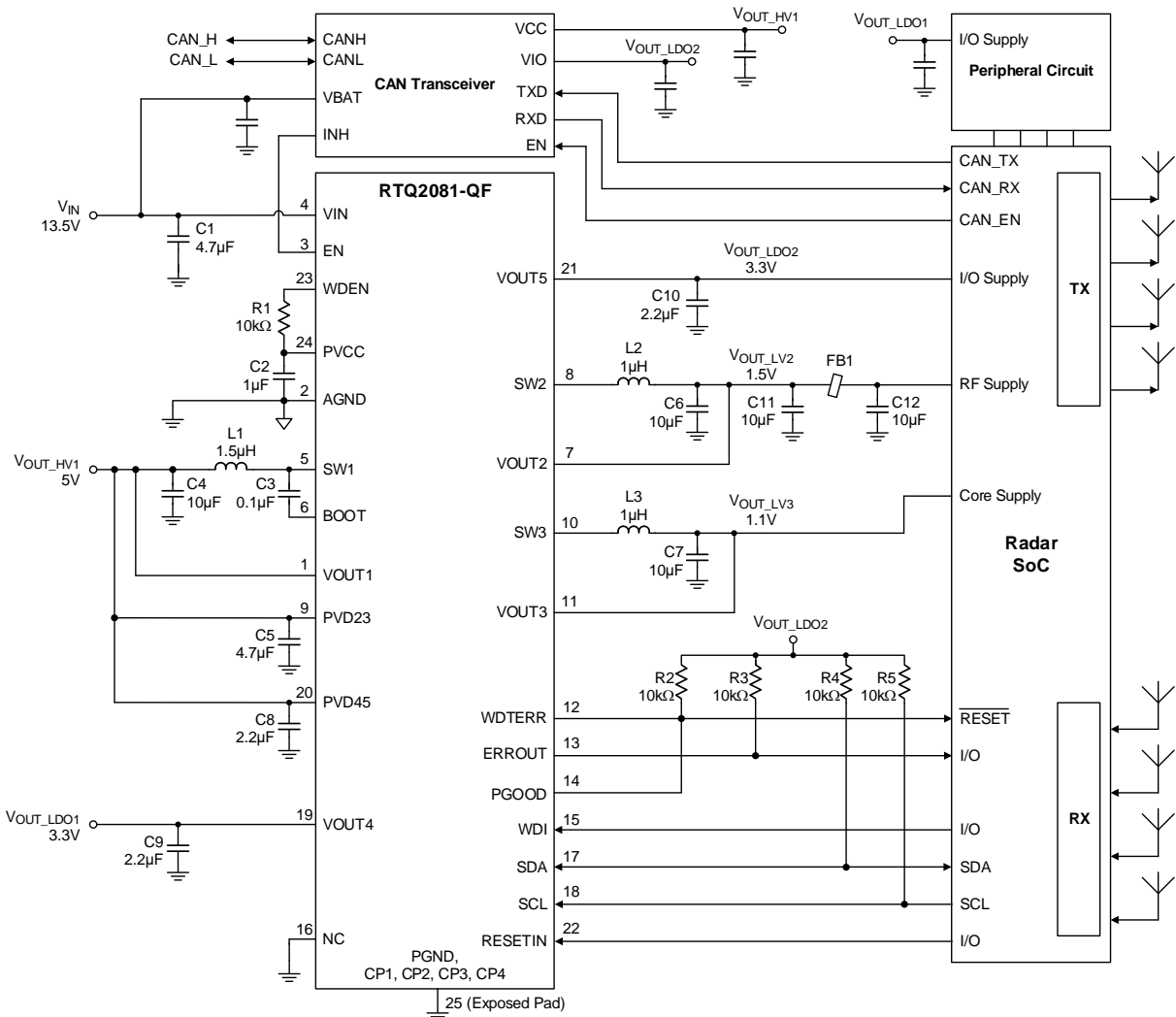
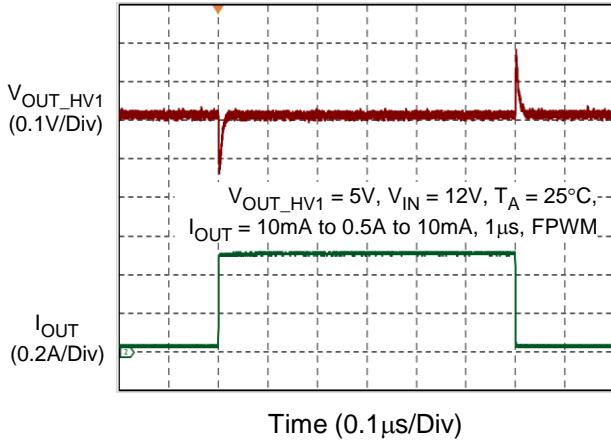


Table 1. Recommended Component List for Evaluation Board

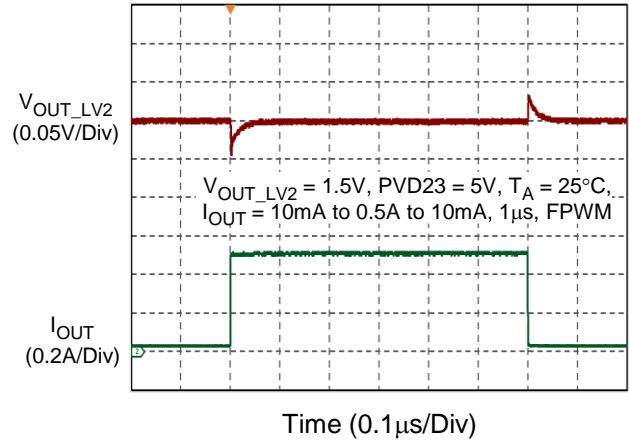
Reference	Qty	Part Number	Description	Package	Manufacturer
C1	1	GCM31CC71H475KA03	4.7μF/50V/X7S	1206	MURATA
C2	1	GCM155C71A105KE38	1.0μF/10V/X7S	0402	MURATA
C3	1	GCM155R71C104KA55	0.1μF/16V/X7R	0402	MURATA
C4, C6, C7, C11, C12	1	GCM21BC71C106KE36	10μF/16V/X7S	0805	MURATA
C5	1	GCM21BR71C475KA73	4.7μF/16V/X7R	0805	MURATA
C8, C9, C10	1	GCM188C71A225KE02	2.2μF/10V/X7S	0603	MURATA
L1	1	TFM201610ALMA1R5MTAA	1.5μH/3.1A/85mΩ	0806	TDK
L2, L3	1	TFM201610ALMA1R0MTAA	1μH/3.7A/50mΩ	0806	TDK
R1, R2, R3, R4, R5	1	MR02X1002FAL	10kΩ/1%	0201	WALSIN
FB1	1	BLM18KG300JH1	30Ω@100MHz/3.3A	0603	MURATA

16 Typical Operating Characteristics

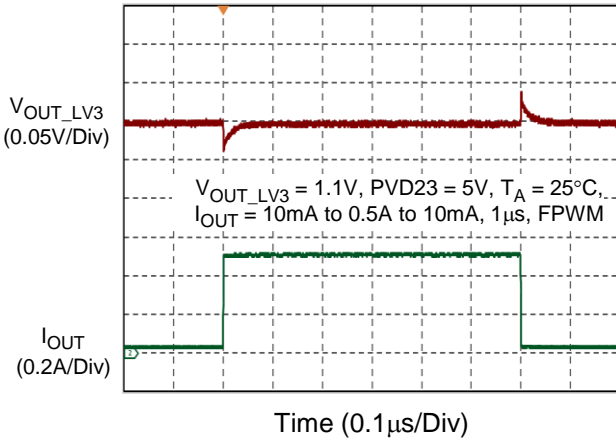
HVBuck1 Load Transient



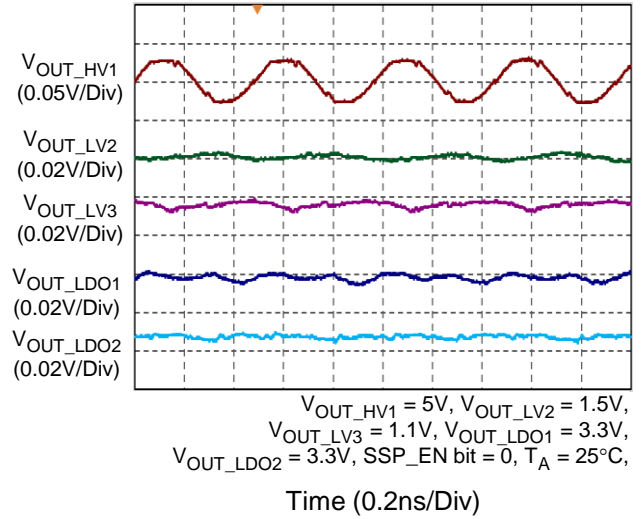
LVBuck2 Load Transient



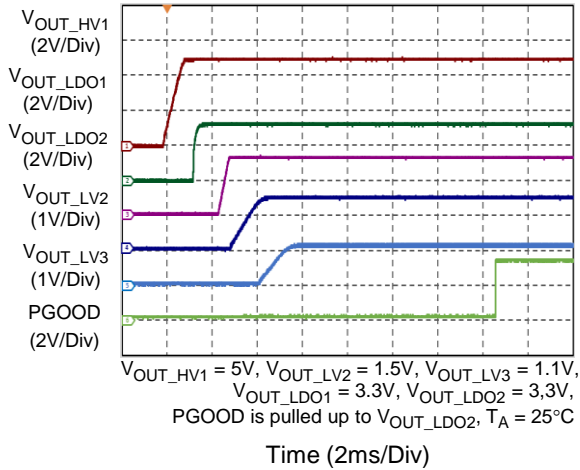
LVBuck3 Load Transient



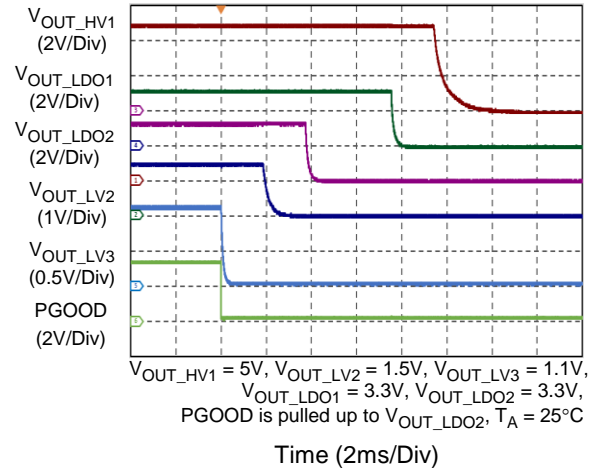
Output Voltage Ripple (Full Load)

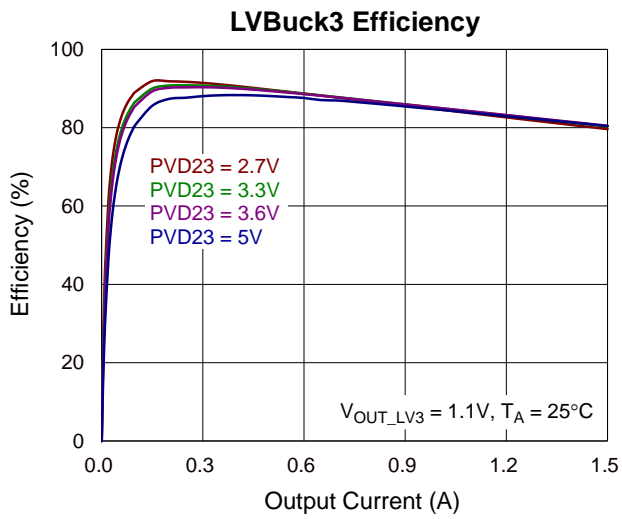
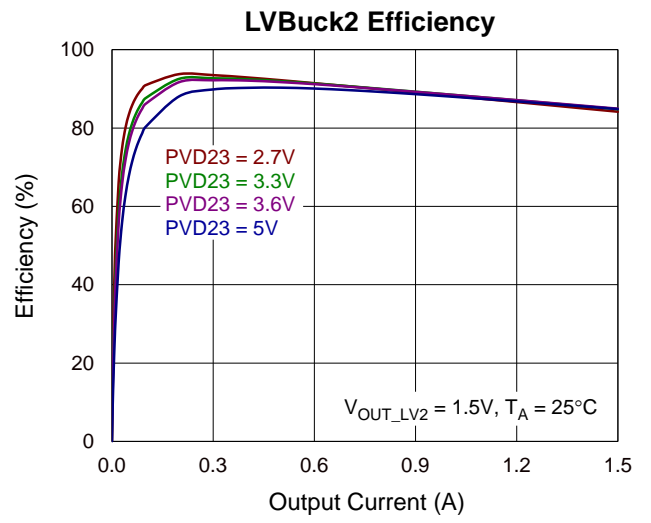
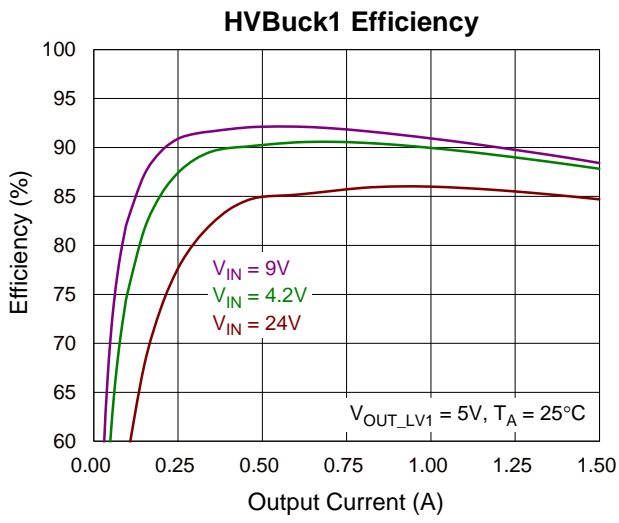


SEQ6 Power-On



SEQ6 Power-Off





17 Operation

The RTQ2081-QF is a highly integrated power management integrated circuit (PMIC) for automotive radar system. It includes three step-down converters (HVBuck1, LVBuck2, LVBuck3) and two generic LDOs (LDO1, LDO2).

17.1 System Undervoltage and Overvoltage Protection

The RTQ2081-QF disables all channels if the V_{IN} voltage falls below the undervoltage lockout falling threshold (V_{UVLO_F}) and the condition lasts for more than 32 μ s. The device initializes its default state after the V_{IN} voltage recovers from undervoltage lockout rising threshold (V_{UVLO_R}).

When the V_{IN} voltage reaches the overvoltage protection rising threshold ($V_{OVP_R_VIN}$), the step-down converters and LDOs are disabled immediately. Then the IC enters the "Regulator-Off" state, and PGOOD and ERROUT change from "H" to "L" to indicate that the IC is in a fault status. When V_{IN} falls below 19.5V and the condition lasts for more than 5 μ s, then the RTQ2081-QF resumes operation automatically.

17.2 Over-Temperature Protection

The RTQ2081-QF features over-temperature warning (OTW) and over-temperature protection (TSD) protection. When the junction temperature exceeds the typical value of 130°C typical value, the OTW function is triggered, and ERROUT changes from "H" to "L" state for indication, but all outputs continue to operate. When the junction temperature exceeds the typical value of 170°C, the TSD function is triggered, disabling all outputs, and the device enters the "Regulator-Off" state. Meanwhile, PGOOD also changes from "H" to "L" state to indicate the IC is in a fault status. The RTQ2081-QF automatically resumes operation once the temperature drops below the TSD level with a 20°C hysteresis band.

17.3 Pre-Regulator

The device integrates a 4.58V linear regulator (PVCC) supplied by V_{IN} to provide power to the internal circuitry. The PVCC is "NOT" allowed to power any other device or circuitry. A 1 μ F decoupling capacitor must be connected between PVCC and AGND to filter the noise, and it needs to be placed as close as possible to the PVCC pin.

17.4 Peak Current Mode Control

The three step-down converters utilize the peak current mode control. At the beginning of each clock cycle, the internal high-side MOSFET turns on to allowing the current to ramp up in the inductor. By comparing the inductor peak current signal with the internal compensation signal derived from the feedback voltage, the turn-on time of high-side and low-side MOSFETs in every switching cycle are determined. In other words, the inductor current is used to control the duty-cycle and output voltage regulation of the converter.

17.5 Spread Spectrum Operation

Due to the periodicity of the switching signal, the energy concentrates at one particular frequency and its N-order harmonics. This partial energy may be emitted as radiation and may cause the EMI issues. The RTQ2081-QF is equipped with a spread spectrum function to mitigate EMI and meet the automotive EMC compliance (CISPR 25). The implemented spread-spectrum function, using a pseudo-random sequence makes the switching frequency vary randomly from 0% to 6%. For example, when the typical switching frequency is 2.1MHz, the switching frequency varies randomly between 2.1MHz and 2.226MHz. Therefore, the RTQ2081-QF can guarantee that the 2.1MHz switching frequency does not fall within the 1.8MHz AM band limit scope of CISPR 25.

17.6 Phase-Shift Operation

The RTQ2081-QF supports phase-shift operation to prevent all step-down converters from switching simultaneously, further reducing the radiation quantity of energy. The phase-shift difference in the clock between each step-down converter automatically changes based on the numbers of enabled channels. For example, when two step-down converters are in use, the initial turn-on time between two high-side MOSFETs has a 180-degree phase difference. Likewise, there is a 120-degree phase difference when three step-down converters are in use.

17.7 Allowable Channel Floating

To save PCB layout space and reduce material cost, the unused low-voltage step-down converters (CH2/CH3) can be left with pins floating, without the need for placing any inductors and output capacitors. The RTQ2081-QF automatically detects the pin status during the power-on procedure to determine whether the channel is used or not. After that, any failure of an unused channel does not affect the device operation.

17.8 Power-Good Indication

The RTQ2081-QF features an open-drain output pin named PGOOD (Power-Good) to indicate the output voltage status of all channels. Connect a pull-up resistor from the PGOOD pin to an external voltage. When the last channel in the power-on sequence reaches 90% of its target output voltage, the PGOOD signal will be pulled high to indicate a “Power-Good” status after a 10ms delay.

17.9 Watchdog Timer Function Monitoring

The RTQ2081-QF features an integrated watchdog timer function that monitors signal inputs received via I²C or WDI kicks from an external system to assess operational status. This function can be configured for either Window Watchdog Timer (WWDT) mode or Simple Watchdog Timer (WDT) mode, depending on the specific requirements of the system application.

Table 2. Unused Channel Pin Connection

Unused Channel	Unused Pin Number	Unused Pin Name	Pin Configuration
LVBuck2	7	VOUT2	Floating
	8	SW2	Floating
	9	PVD23	Connect to a fixed stable voltage
LVBuck3	9	PVD23	Connect to a fixed stable voltage
	10	SW3	Floating
	11	VOUT3	Floating
LDO1	19	VOUT4	Floating with minimum effective output capacitance
	20	PVD45	Connect to a fixed stable voltage
LDO2	20	PVD45	Connect to a fixed stable voltage
	21	VOUT5	Floating with minimum effective output capacitance
ERROUT	13	ERROUT	Connect to a fixed stable voltage via a pull-up resistor
PGOOD	14	PGOOD	Floating
NC	16	NC	Connect to ground
WDI	15	WDI	Connect to ground

Unused Channel	Unused Pin Number	Unused Pin Name	Pin Configuration
I ² C	17	SDA	Connect to ground
	18	SCL	Connect to ground
RESETIN	22	RESETIN	Connect to ground
WDEN	23	WDEN	Connect to ground

18 Application Information

([Note 9](#))

18.1 Device and Channel Enable Control

There is a hardware enable pin, EN, to control the RTQ2081-QF. When the supply voltage V_{IN} reaches the power-on reset level of 2.7V (typical) and EN is in a high state, the device is enabled and ready to receive I²C commands for configuration. When V_{IN} continues to rise higher than the UVLO rising voltage and the SEQ_CTRL register at 0x00[0] = 1, the power-on sequence starts. The channels are sequenced to power-off if the EN state changes to low or the SEQ_CTRL register at 0x00[0] = 0. All channels shut down immediately without any sequence once V_{IN} falls below UVLO falling voltage.

18.2 Device Register Configuration Control

Write access to the registers or bits marked as "CFG_LOCK (Configured Lock)" is restricted via the TM_PASS_CODE registers at 0x20 and 0x21. Before the configuration of the registers can be changed, the correct password must be written to enter guest mode and unlock the control registers. Once changes are complete, an incorrect password must be written to leave guest mode and lock the control registers, avoiding unexpected operation.

18.3 Device State Machine

There are seven main states listed in the [Table 3](#).

Table 3. Device State

State	Description	Entry	Exit
Power-Off	The device is in non-operation state.	<ul style="list-style-type: none"> $V_{IN} \leq 2.5V$ (typical) <u>From Regulator-Off</u> EN = L 	<ul style="list-style-type: none"> $V_{IN} \geq 2.7V$ (typical) AND EN = H
Regulator-Off	The device loads OTP for the default setting and passes the OTP CRC checksum value comparison. All channels are still disabled, and the PGOOD/ERROUT signals are driven to a low state.	<p><u>From Power-Off</u></p> <ul style="list-style-type: none"> Pass the OTP CRC checksum value comparison <p><u>From Standby/Power-On</u></p> <ul style="list-style-type: none"> EN = L $V_{IN} \leq V_{UVLO_F}$ Fault event (V_{IN} OVP, VPVD23 OVP, VPVD45 OVP, TSD) RESET behavior (RESETIN, RESET bit) <p><u>From Active/Alarm</u></p> <ul style="list-style-type: none"> EN = L $V_{IN} \leq V_{UVLO_F}$ Fault event (V_{IN} OVP, VPVD23 OVP, VPVD45 OVP, TSD) RESET behavior (RESETIN, RESET bit) SEQ_CTRL_bit 0x00[0] = 0 <p><u>From Fail-Safe</u></p> <ul style="list-style-type: none"> EN = L $V_{IN} \leq V_{UVLO_F}$ RESET behavior (RESETIN, RESET bit) REBOOT_ACT 0x00[1] = 1 	<p><u>To Power-Off</u></p> <ul style="list-style-type: none"> $V_{IN} \leq 2.5V$ (typical) EN = L <p><u>To BIST</u></p> <ul style="list-style-type: none"> $V_{IN} \geq V_{UVLO_R}$ AND no fault event (V_{IN} OVP, VPVD23 OVP, VPVD45 OVP, TSD) AND EN = H.
Standby	The device passes built-in self-test (BIST) and waits for an I ² C command to enable all channels.	BIST pass	<p><u>To Regulator-Off</u></p> <ul style="list-style-type: none"> EN = L $V_{IN} \leq V_{UVLO_F}$ Fault event (V_{IN} OVP, VPVD23 OVP, VPVD45 OVP, TSD) <p><u>To Power-On</u></p> <ul style="list-style-type: none"> SEQ_CTRL 0x00[0] = 1 AND No RESET behavior (RESETIN, RESET bit)

State	Description	Entry	Exit
Power-On	Channel power-on procedure gets started.	<p><u>From Standby</u> SEQ_CTRL 0x00[0] = 1 AND No RESET behavior (RESETIN, RESET bit)</p>	<p><u>To Regulator-Off</u></p> <ul style="list-style-type: none"> • EN = L • $V_{IN} \leq V_{UVLO_F}$ • Fault event (V_{IN} OVP, VPVD23 OVP, VPVD45 OVP, TSD) <p><u>To Active</u></p> <ul style="list-style-type: none"> • All enabled channels output voltages rise to 90% of the target values <p><u>To Fail-Safe</u></p> <ul style="list-style-type: none"> • Fault event (CH V_O UVP, CH V_O OVP) if the register 0x0F = 1Fh, 0x10 = 1Fh • Fault event (CH OCP)
Active	All enabled channels' output voltages rise to 90% of the target value. The PGOOD and ERROUT signals change to a high state to indicate the power status and any fault events. The RESEIN and WDT functions are activated after the PGOOD signal changes to a "H" state.	<p><u>From Power-On</u></p> <ul style="list-style-type: none"> • All enabled channels output voltages rise to 90% of the target values <p><u>From Alarm</u></p> <ul style="list-style-type: none"> • All fault registers (0x11 to 0x15) event = 0 	<p><u>To Regulator-Off</u></p> <ul style="list-style-type: none"> • EN = L • $V_{IN} \leq V_{UVLO_F}$ • Fault event (V_{IN} OVP, VPVD23 OVP, VPVD45 OVP, TSD) • RESET behavior (RESETIN, RESET bit) • WDT fault triggers if WDT_FAULT 0xAD[1]=1 • SEQ_CTRL 0x00[0] = 0 <p><u>To Alarm</u></p> <ul style="list-style-type: none"> • Fault event (CH V_O UVP, CH V_O OVP) if register 0x0F = 00h, 0x10 = 00h • WDT fault triggers if WDT_FAULT 0xAD[1]=0 • Fault event (OTW) • Any fault register (0x11 to 0x15, except 0x12[6]) event = 1 <p><u>To Fail-Safe</u></p> <ul style="list-style-type: none"> • Fault event (CH V_O UVP, CH V_O OVP) if register 0x0F = 1Fh, 0x10 = 1Fh • Fault event (CH OCP)

State	Description	Entry	Exit
Alarm	<p>When a fault event is detected but the channel is not turned off, the PGOOD signal keeps in a high state and the ERROUT goes low for a warning.</p> <p>In the event of a Watchdog Timer (WDT) fault, the WDTERR signal will transition to a low state for a duration of 200μs before returning to the high ("H") state.</p>	<p><u>From Active</u></p> <ul style="list-style-type: none"> Fault event (CH VO UVP, CH VO OVP) if register 0x0F = 00h, 0x10 = 00h Fault event (WDT fault) if WDT_FAULT 0xAD[1] = 0 Fault event (OTW) Any fault register (0x11 to 0x15, except 0x12[6]) event = 1 	<p><u>To Regulator-Off</u></p> <ul style="list-style-type: none"> EN = L VIN \leq VUVLO_F Fault event (VIN OVP, VPVD23 OVP, VPVD45 OVP, TSD) RESET behavior (RESETIN, RESET bit) SEQ_CTRL 0x00[0] = 0 <p><u>To Active</u></p> <ul style="list-style-type: none"> All fault registers (0x11 to 0x15) event = 0 <p><u>To Fail-Safe</u></p> <ul style="list-style-type: none"> Fault event (CH VO UVP, CH VO OVP) if register 0x0F = 1Fh, 0x10 = 1Fh Fault event (CH OCP)
Fail-Safe	<p>When a fault event is detected and all channels are turned off, the PGOOD signal changes to a low state to indicate the power status. The ERROUT signal also changes to a low state to indicate a fault has been detected.</p>	<ul style="list-style-type: none"> BIST failure Fault event (CH VO UVP, CH VO OVP) if register 0x0F = 1Fh, 0x10 = 1Fh Fault event (CH OCP) 	<p><u>To Regulator-Off</u></p> <ul style="list-style-type: none"> VIN \leq VUVLO_F EN = L RESET behavior (RESETIN, RESET bit) REBOOT_ACT 0x00[1] = 1

18.4 Power Sequence and Interval Time Setting

The RTQ2081-QF offers seven power-on sequencing options, as shown in Table 4. The power sequence and interval time between channels can be programmed via I²C, but only if the SEQ_CTRL register at 0x00[0] is cleared to 0. Adjustments made to the power sequence register at 0x02[2:0] and the interval time register at 0x02[6:3] will become effective at the next power-up event. For permanent settings, the RTQ2081-QF includes the OTP36 register at 0xE4[6:0], which provides OTP (one-time programmable) options for setting the power sequence and interval times as the default upon manufacture.

Table 4. Power-On Sequence

SEQ No.	Sequential Power-On Sequence
SEQ0	CH1 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{ON_Td}$ CH3 $\xrightarrow{ON_Td+250\mu s}$ CH4 $\xrightarrow{ON_Td+1ms+tPGOOD_DLY}$ PGOOD
SEQ1	CH1 $\xrightarrow{ON_Td+550\mu s}$ CH4 $\xrightarrow{ON_Td}$ CH3 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{ON_Td+1ms+tPGOOD_DLY}$ PGOOD
SEQ2	CH1 $\xrightarrow{ON_Td+550\mu s}$ CH4 $\xrightarrow{2*(ON_Td)+1ms}$ CH3 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{tPGOOD_DLY}$ PGOOD
SEQ3	CH1 $\xrightarrow{ON_Td}$ CH2, CH3, CH4 $\xrightarrow{tPGOOD_DLY}$ PGOOD
SEQ4	CH1 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{ON_Td}$ CH3 $\xrightarrow{ON_Td+250\mu s}$ CH4 $\xrightarrow{ON_Td}$ CH5 $\xrightarrow{ON_Td+1ms+tPGOOD_DLY}$ PGOOD
SEQ5	CH1 $\xrightarrow{ON_Td+550\mu s}$ CH4 $\xrightarrow{ON_Td}$ CH3 $\xrightarrow{ON_Td}$ CH5 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{ON_Td+1ms+tPGOOD_DLY}$ PGOOD
SEQ6	CH1 $\xrightarrow{ON_Td+550\mu s}$ CH4 $\xrightarrow{2*(ON_Td)+1ms}$ CH5 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{ON_Td}$ CH3 $\xrightarrow{tPGOOD_DLY}$ PGOOD
SEQ7	CH1 $\xrightarrow{ON_Td+550\mu s}$ CH4 $\xrightarrow{2*(ON_Td)+1ms}$ CH3 $\xrightarrow{ON_Td}$ CH2 $\xrightarrow{ON_Td}$ CH5 $\xrightarrow{tPGOOD_DLY}$ PGOOD

Note 8. Even if CH2 or CH3 is configured to be disabled by default, the turn-on delay (ON_Td) for CH2 or CH3 is still considered in the internal time counting for the power-on sequence.

18.5 Power-On/Off Control

The RTQ2081-QF's power sequence can be flexibly managed through various methods, including the use of V_{UVLO}, the EN pin, the SEQ_CTRL register bit at 0x00[0], or the RESETIN pin, to cater to diverse requirements and applications. The power-off sequence is executed in the reverse order of the power-on sequence.

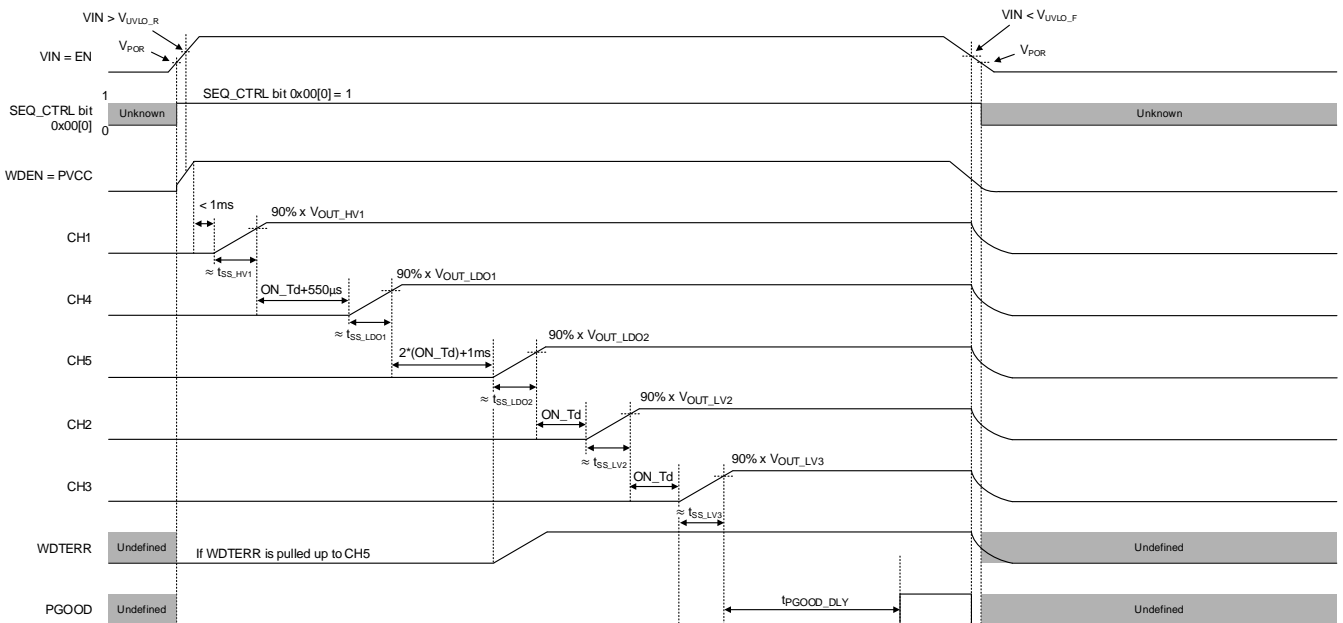


Figure 2. SEQ6 Power Sequence Example Using V_{UVLO} (VIN = EN)

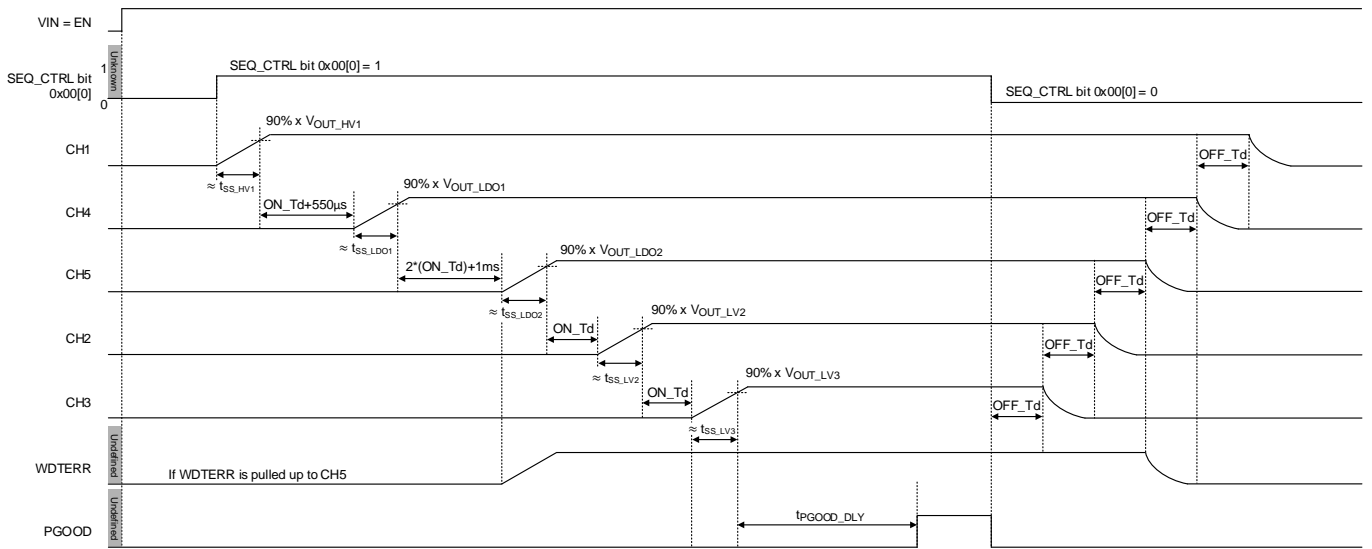


Figure 3. SEQ6 Power Sequence Example 1 Using SEQ_CTRL

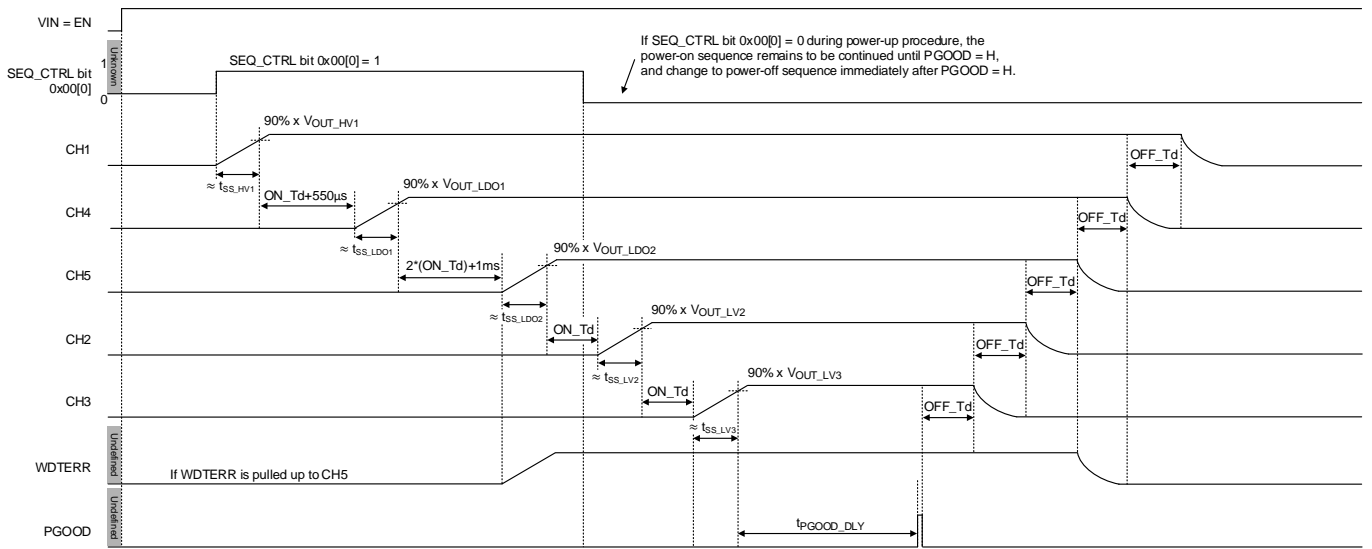


Figure 4. SEQ6 Power Sequence Example 2 Using SEQ_CTRL

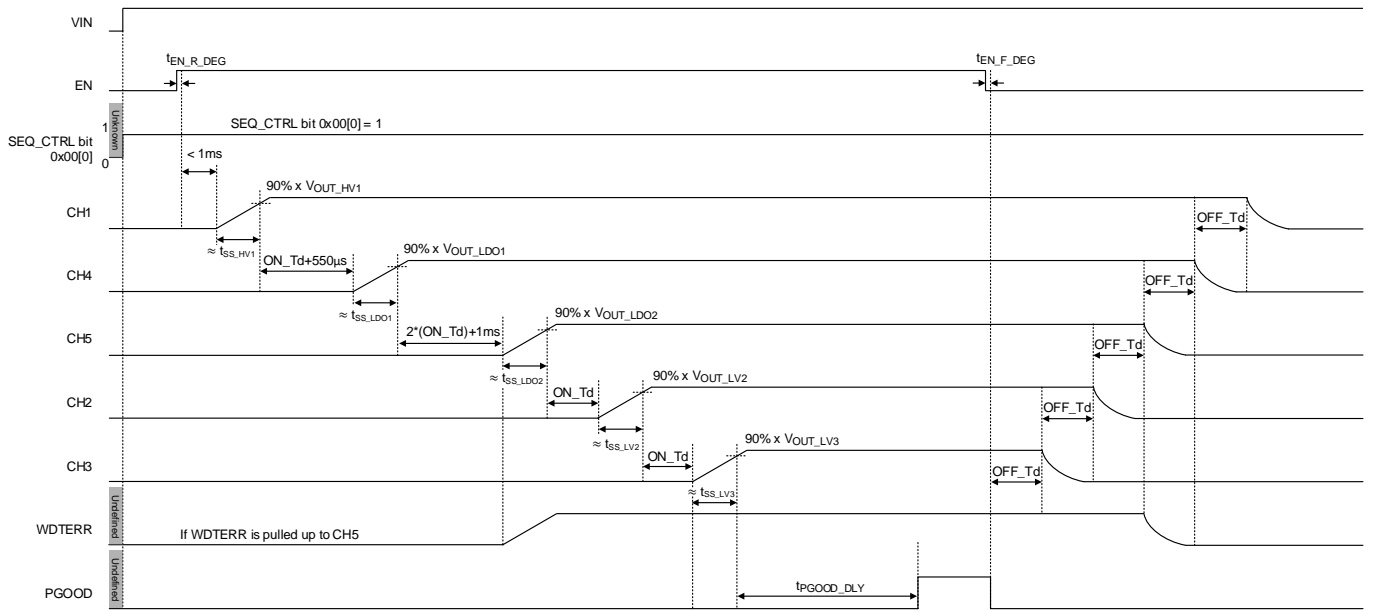


Figure 5. SEQ6 Power Sequence Example 1 Using EN

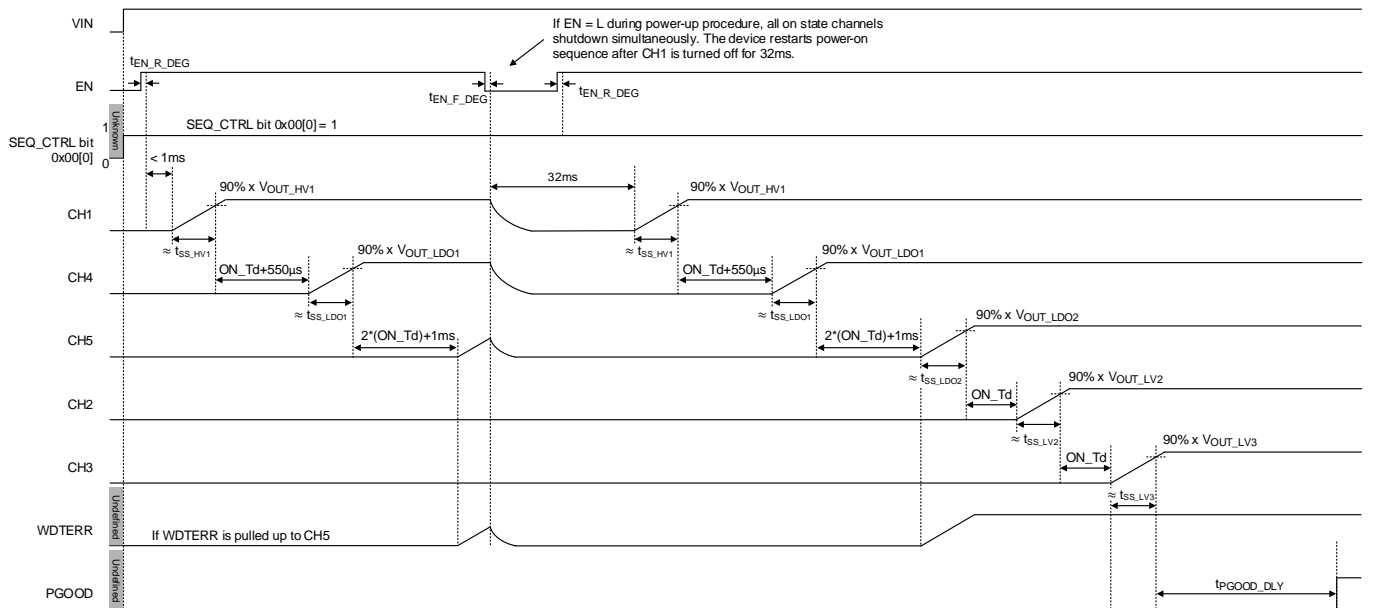


Figure 6. SEQ6 Power Sequence Example 2 Using EN

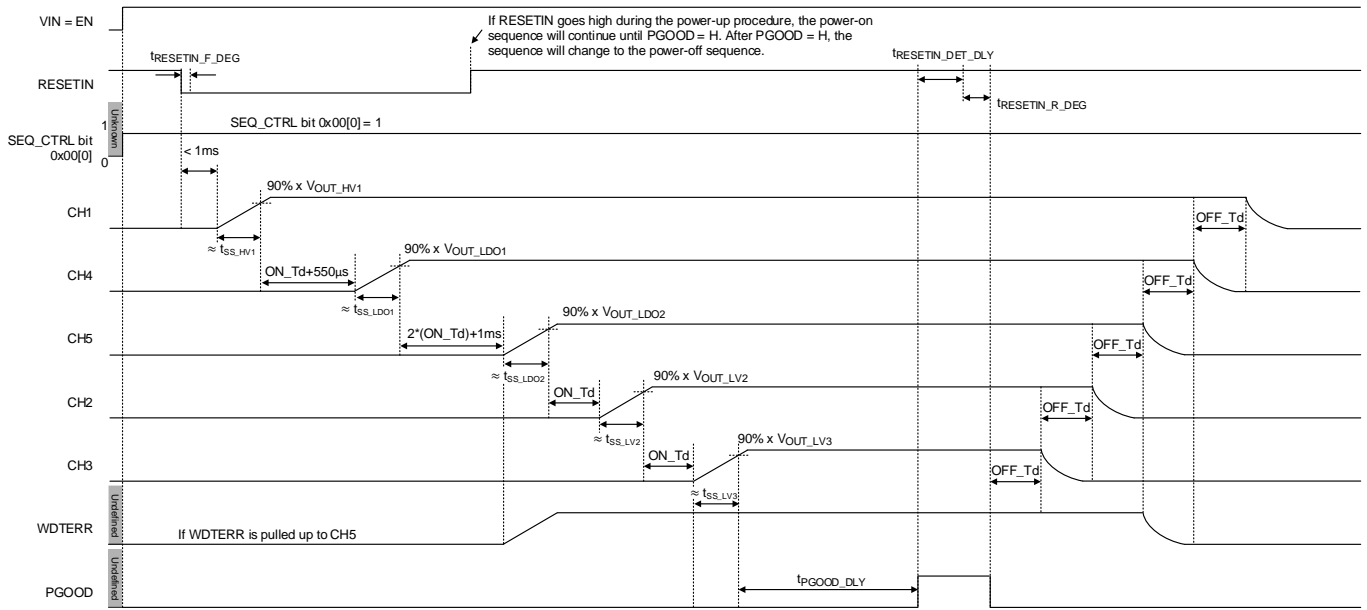


Figure 7. SEQ6 Power Sequence Example Using RESETIN

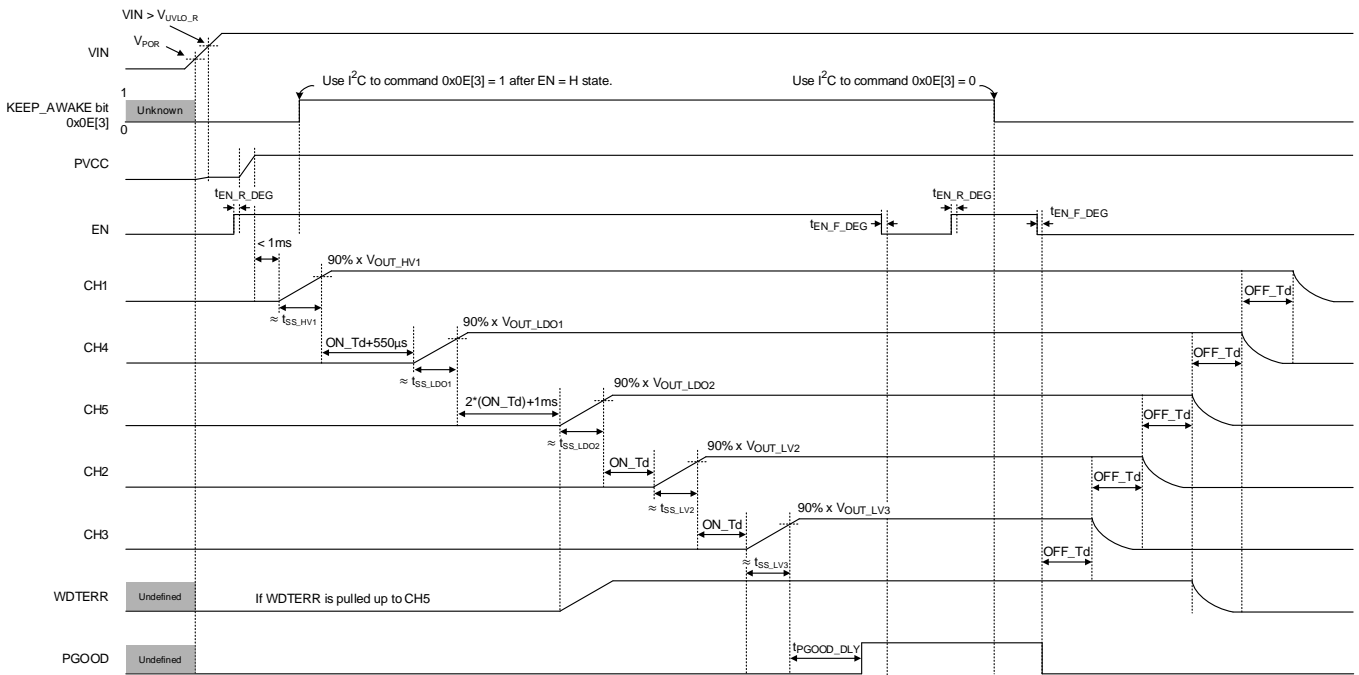


Figure 8. SEQ6 Power Sequence with KEEP_AWAKE Function

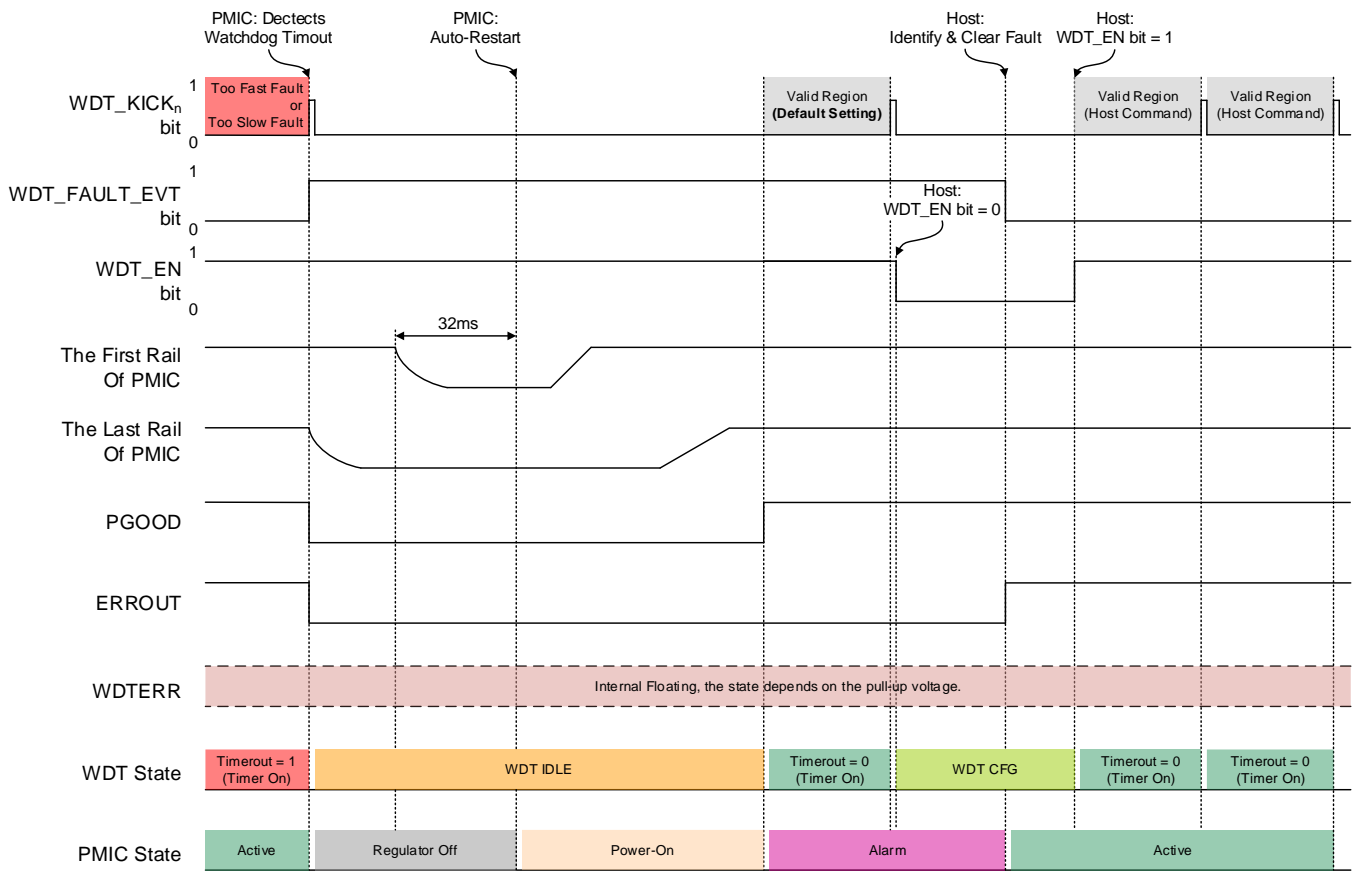


Figure 9. WDT State Flow – PMIC Auto-Restart by I²C Kicks (WDEN = PVCC, WDT_FAULT bit = 1)

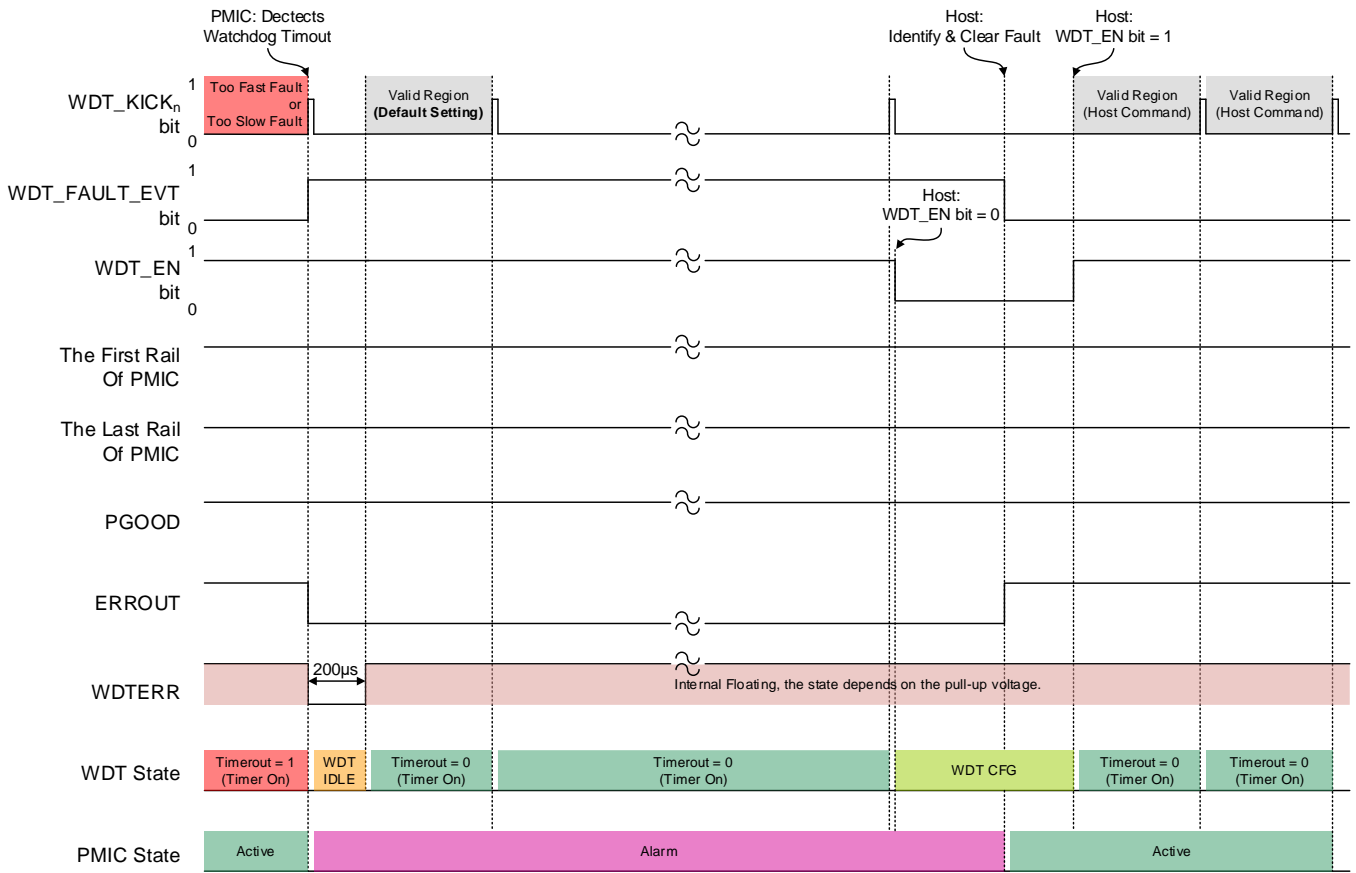


Figure 10. WDT State Flow – PMIC's WDTERR Toggles by I²C Kicks (WDEN = PVCC, WDT_FAULT bit = 0)

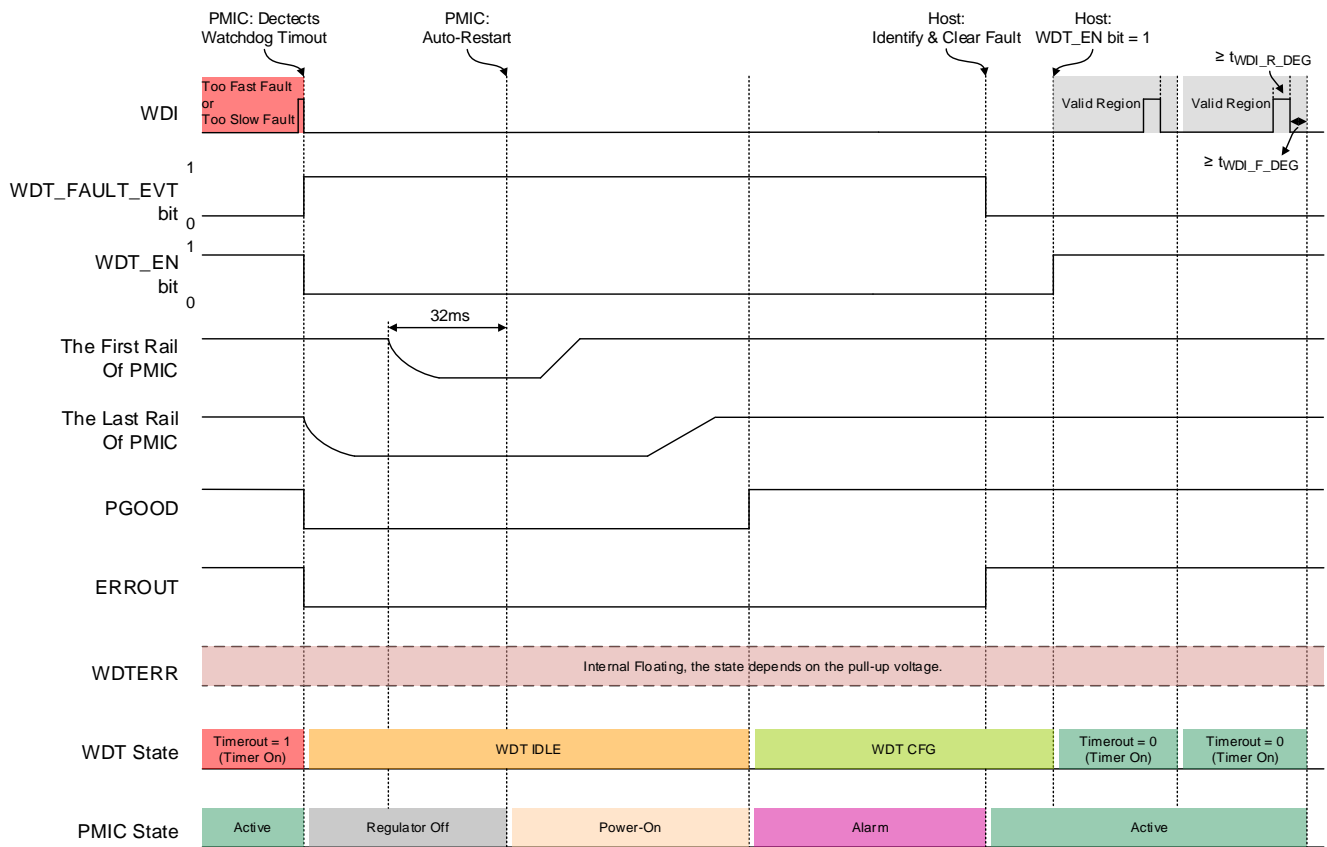


Figure 11. WDT State Flow – PMIC Auto-Restart by WDI (WDEN = GND, WDT_FAULT bit = 1)

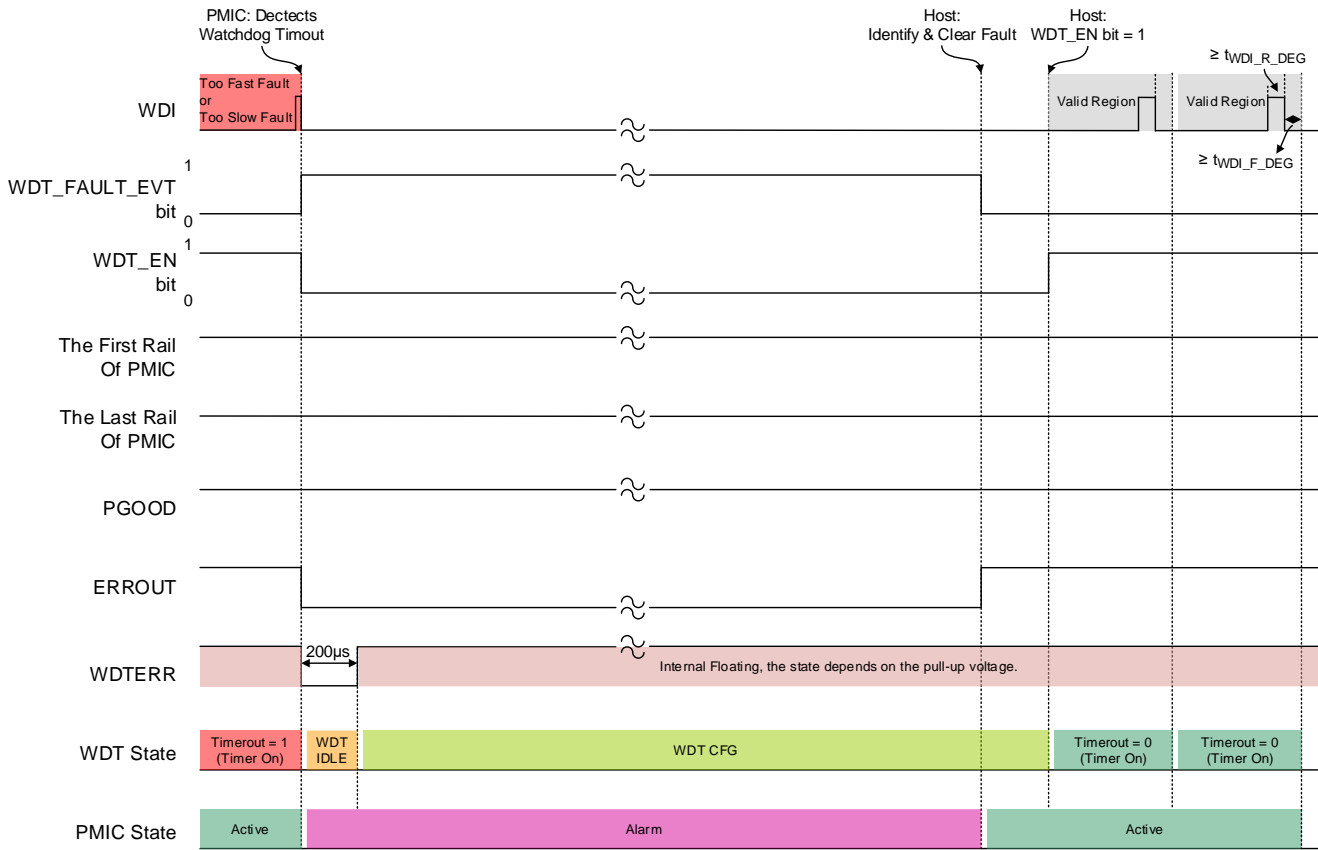


Figure 12. WDT State Flow – PMIC’s WDERR Toggles by WDI (WDEN = GND, WDT_FAULT bit = 0)

18.6 Output Voltage Setting

The output voltage settings of all rails are controlled through I²C by configuring the relevant registers. The RTQ2081-QF is also equipped with OTP37 to OTP39 registers of 0xE5 to 0xE7[7:6] to provide one-time programmable settings for the corresponding output voltages as the factory default settings.

- **HVBuck1, LVBuck2 and LVBuck3**

HVBuck1 output voltage can be set via the register at 0x03[3:0] from 2.7V to 5V, with a default voltage of 5V.

LVBuck2 output voltage can be set via the register at 0x04[4:0] from 0.6V to 1.9V, with a default voltage of 1.5V.

LVBuck3 output voltage can be set via the register at 0x05[4:0] from 0.6V to 1.9V, with a default voltage of 1.1V.

- **LDO1 and LDO2**

LDO1 output voltage can be set via register of 0x06[4:0] from 1.8V to 3.5V and the default voltage of 3.3V.

LDO2 output voltage can be set via register of 0x07[3:0] from 1.8V to 3.3V and the default voltage of 3.3V.

18.7 Watchdog Timer Function (WDT)

The RTQ2081-QF comes with a configurable watchdog timer (WDT) function, tailored for diverse application needs. Through I²C programming, system designers have the flexibility to:

- (1) Select between window watchdog timer (WWDT) and simple watchdog timer (WDT) modes.
- (2) Decide on kicking the watchdog via I²C commands or an external WDI pin signal.
- (3) Choose the fault response based on the WDT_FAULT bit 0xAD[1]. When a WDT fault occurs, the system has the option to either issue an alert indication through the WDERR pin and then enter the "Alarm" state, or to shut off the regulators and perform an automatic restart.

Below are WDT state flow diagram and WDT timing diagrams:

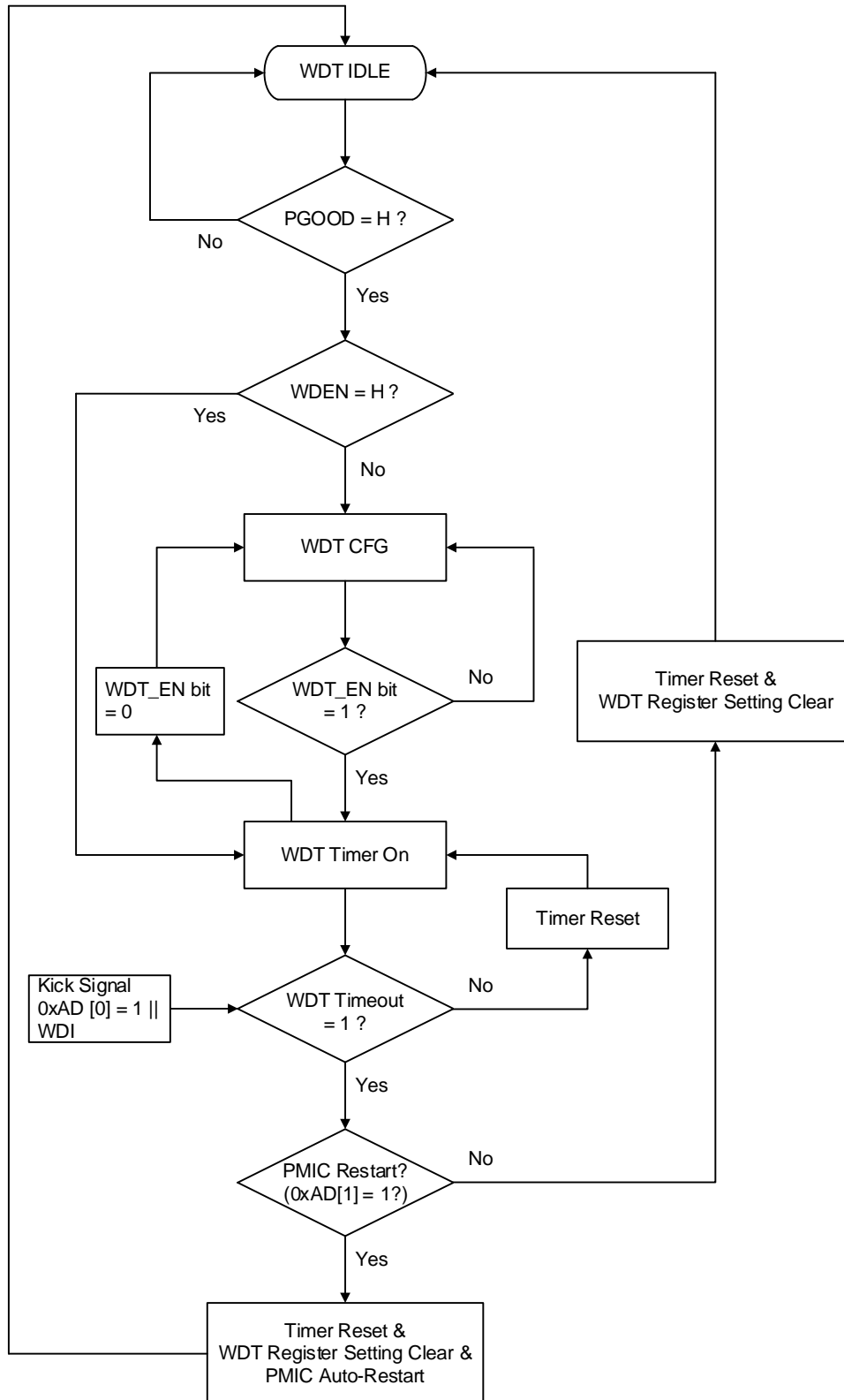


Figure 13. WDT State Flow Diagram

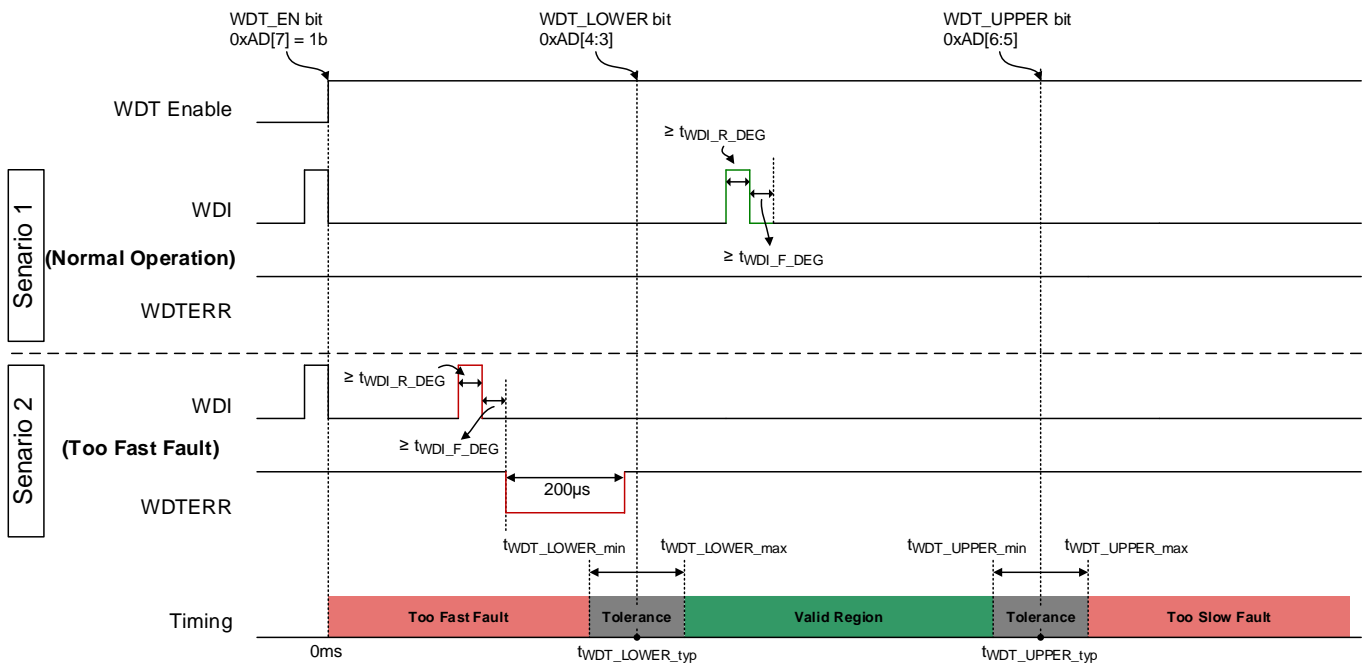


Figure 14. WWDT Timing Diagram (WDT_FAULT bit = 0)

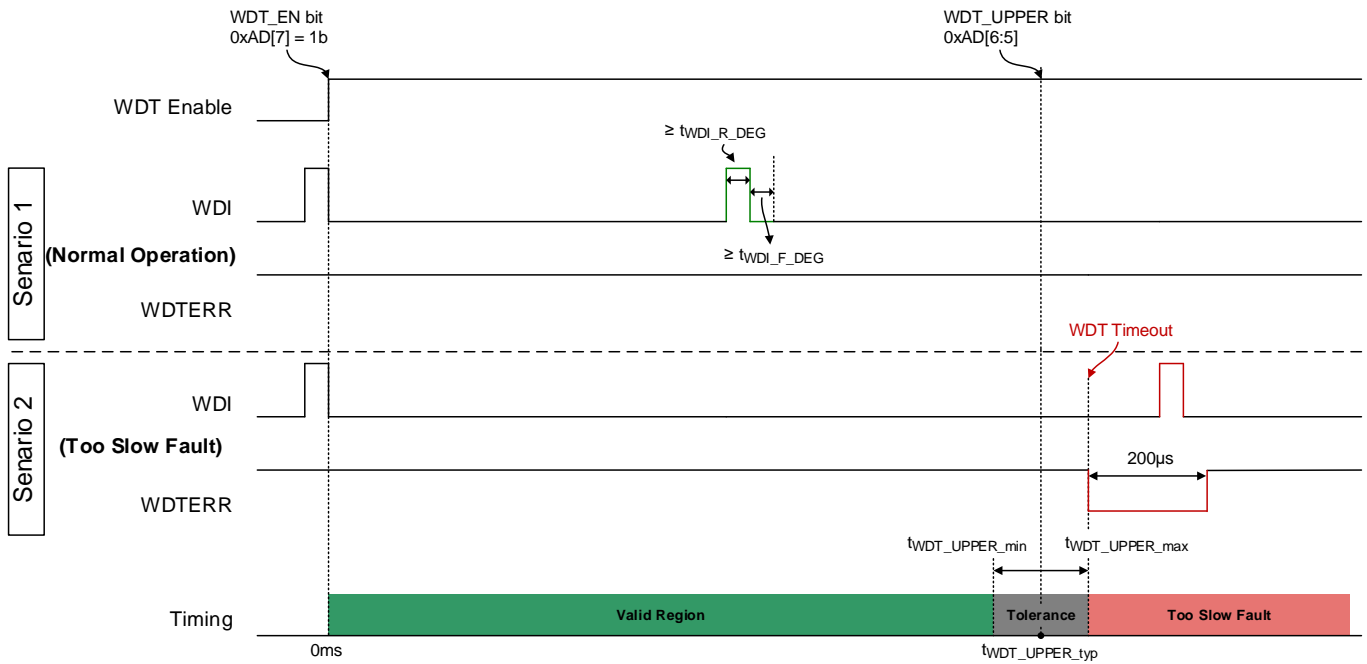


Figure 15. Simple WDT Timing Diagram (WDT_FAULT bit = 0)

Additionally, the RTQ2081-QF's watchdog timer (WDT) function remains inactive during the initial power-on phase, only starting its count when the power-good (PGOOD) signal shifts from low ("L") to high ("H"). Moreover, should the RTQ2081-QF experience even a single WDT fault, it will automatically reset the WDT settings to their default values. This characteristic is crucial for system designers to consider while incorporating the RTQ2081-QF into their designs.

Note that:

- Using I²C and WDI to send kick commands simultaneously is not permitted. It is recommended to select either I²C or WDI as the primary method of control.
- The state of the WDEN pin must be set to either high or low prior to initiating the power-on procedure. Once the power-on sequence has begun, any changes to the state of the WDEN pin are prohibited. To alter the Enable or Disable state of the WDT subsequently, it must be set through the WDT_EN bit 0xAD[7].

18.8 Reset Function

The RTQ2081-QF features a dedicated external hardware reset pin, RESETIN, and a RESET register located at 0x0D[4] for resetting the device. The RESET function is triggered once the PGOOD signal remains high for 100 microseconds.

The RESET_ACT register bit at 0x0D[3] offers two reset behaviors:

- With 0x0D[3] = 0, it resets all registers except for sequence control at 0x02[4:0] and fault events logs at 0x11 to 0x15. Output rails are disabled per sequence, but fault events logs can be read out by the ECU after reset.
- With 0x0D[3] = 1, it resets all registers to defaults except for sequence control at 0x02[4:0]. Output rails are disabled following the sequence.

18.9 Protection Features

The RTQ2081-QF incorporates a suite of protection features designed to protect the device from potential damage arising from abnormal operations or fault conditions, including abnormal voltage, overload, short-circuit, and thermal issues.

18.9.1 Channel Output Undervoltage Protection (UVP)

The RTQ2081-QF is designed with four Undervoltage Protection (UVP) thresholds, adjustable through the CH_UVP1_CFG 0x08[7:0] and CH_UVP2_CFG 0x09[5:4] registers. The deglitch time for output UVP is configurable via CH_UVP2_CFG 0x09[3:0]. Should any bit within PROTEC1_CFG 0x0F[4:0] be activated (set to 1), the device will disable all outputs and shift into a Fail-Safe state when a UV fault is detected. Conversely, if PROTEC1_CFG 0x0F[4:0] is entirely unset (all zeros), the device keeps channels active but enters an Alarm state upon UV fault detection. The UV fault occurrences are logged in the CH_UV_EVT 0x13[4:0] register, independent of the PROTEC1_CFG 0x0F[4:0] configuration. Default UVP behavior is pre-set by the OTP35 register at 0xE3[1]. The device can be reset using various methods, which are specified in [Table 3](#).

18.9.2 Channel Output Overvoltage Protection (OVP)

The RTQ2081-QF is designed with four Overvoltage Protection (OVP) thresholds, adjustable through the CH_OVP1_CFG 0x0A[7:0] and CH_OVP2_CFG 0x0B[5:4] registers. The deglitch time for output OVP is configurable via CH_OVP2_CFG 0x0B[3:0]. Should any bit in PROTEC2_CFG 0x10[4:0] be set to 1, the device shuts down all outputs and transitions into the Fail-Safe state upon detecting an OV fault in any channel. Conversely, with all bits in PROTEC2_CFG 0x10[4:0] set to 0 during an OV fault, the device continues operation without disabling any channels, but enters the Alarm state. The OV fault events are logged in the CH_OV_EVT 0x14[4:0] register, independent of PROTEC2_CFG 0x10[4:0] settings. Default OVP behavior is pre-set by the OTP35 register at 0xE3[2]. The device can be reset using various methods, which are specified in [Table 3](#).

18.9.3 Channel Overcurrent Protection (OCP)

This section describes HVBuck1, LVBuck2, LVBuck3, LDO1, and LDO2.

18.9.3.1 HVBuck1, LVBuck2, and LVBuck3

The step-down converter features a cycle-by-cycle protection mechanism that limits the peak current of the high-side MOSFET, effectively preventing excessive inductor current, even beyond the inductor's saturation current specification. Should overcurrent be detected, the controller instantly shuts off the high-side MOSFET and then turns on the low-side MOSFET to keep the inductor current within the peak limit. Once the inductor current dips below the valley limit, the high-side MOSFET is allowed to switch back on. Continuous overcurrent detection exceeding the deglitch time will cause the device to shut off all channels and enter the Fail-Safe state. The device can be reset using various methods, which are specified in [Table 3](#).

18.9.3.2 LDO1 and LDO2

When the load exceeds the current-limit threshold, the output current is regulated to stay at this limit. If the overcurrent condition persists beyond the deglitch time, the device will disable all channel outputs immediately and enter the Fail-Safe state. The device can be reset using various methods, which are specified in [Table 3](#).

18.9.4 Channel Input Overvoltage Protection (OVP)

If the input voltage of PVD23 or PVD45 reaches the overvoltage protection level, the IC will shut off all channel outputs, record the fault events in the register, and enter the Regulator-Off state. Once the input voltage falls beneath the overvoltage threshold, taking hysteresis taken account, the IC will automatically re-power on.

18.9.5 Built-In Self-Test

The RTQ2081-QF is designed with a Built-In Self-Test (BIST) capability. Before activating the power rails, the device runs a series of tests on its internal circuits to confirm the integrity of its safety mechanisms. If the BIST does not pass, the device will enter the Fail-Safe state immediately, without powering the rails. In this event, the BIST_FAULT_EVT register at 0x11[6] will be set to 1, indicating the occurrence of a BIST failure.

18.9.6 ERROUT Indication

The ERROUT pin on the RTQ2081-QF serves as an error indicator with an open-drain configuration, requiring an external pull-up resistor. Should the RTQ2081-QF detect a fault while in the Active state, it will pull the ERROUT signal low. Furthermore, the RTQ2081-QF continuously monitors the ERROUT pin to identify any open-drain logic faults. The fault event will be recorded by the register bit at 0x12[6].

18.9.7 OTP Register CRC (Cyclic Redundancy Check)

Upon the EN pin transitioning to a high state and the supply voltage VIN exceeding the typical power-on reset threshold of 2.7V (typical), the device initiates by loading OTP data, thereby resetting all registers to their default settings. Simultaneously, the CRC controller starts verifying the OTP registers' integrity through a CRC check. It calculates the checksum of the OTP registers and compares it with the pre-stored checksum in OTP40. Should a checksum discrepancy be detected, the device maintains a Power-Off state and sets the OTP_CRC_EVT register at 0x11[5] to 1, serving as an error indication.

18.9.8 Device Configuration Register CRC

If the ECU changes the registers for reconfiguring new settings, the CRC controller performs a CRC to verify the integrity of the related registers. If a checksum error is detected, the device remains the current settings without any re-configuration. The CRC controller uses the standard CRC-8 polynomial to calculate the checksum value, which is $X^8 + X^2 + X + 1$. The CRC controller checks the CRC of the registers in an 8-bit string.

Table 5. Protection List

Channel	Type	Threshold (Typical)	Deglitch Time (Typical)	Channels Behavior	Reset and Threshold (Typical)
Base	BIST	NA	NA	All channels stay disabled	Refer to Table 3 . (Fail-Safe state)
	OTP CRC	NA	NA	All channels stay disabled	$V_{IN} \leq 2.5V$ or $EN = L$
System	UVLO	$V_{IN} \leq 4.3V$ (after IC operation)	32 μ s	Disable all channels	$V_{IN} \geq 5V$ (TOP_CFG [4:3] = 2'b00)
	OVP	$V_{IN} \geq 25.5V$	5 μ s	Disable all channels	$V_{IN} \leq 19.5V$, Auto-recovery
	OTW	$T_J \geq 130^\circ C$	5 μ s	Keep all channels in operation	Refer to Table 3 . (Alarm state)
	TSD	$T_J \geq 170^\circ C$	5 μ s	Disable all channels	$T_J \leq 150^\circ C$, Auto-recovery
	ERRROUT	ERRROUT open-drain logic error	NA	Keep all channels in operation	Refer to Table 3 . (Alarm state)
	I ² C CRC	NA	NA	Keep all channels in operation	NA
CH1 HVBuck1	UVP	$V_{OUT_HV1} \leq V_{OUT_HV1} \times 80\%$	50 μ s	If 0x0F[4] = 0, keep all channels in operation	If 0x0F[4] = 0, refer to Table 3 . (Alarm state)
				If 0x0F[4] = 1, disable all channels and latch off	If 0x0F[4] = 1, refer to Table 3 . (Fail-Safe state)
	OVP	$V_{OUT_HV1} \geq V_{OUT_HV1} \times 110\%$	50 μ s	If 0x10[4] = 0, keep all channels in operation	If 0x10[4] = 0, refer to Table 3 . (Alarm state)
				If 0x10[4] = 1, disable all channels and latch off	If 0x10[4] = 1, refer to Table 3 . (Fail-Safe state)
	OCP	$I_{L1_peak} \geq 2.5A$	1ms	Cycle-by-cycle detection If the condition persists for 1ms, all channels will be disabled, and the device will latch off	Refer to Table 3 . (Fail-Safe state)

Channel	Type	Threshold (Typical)	Deglitch Time (Typical)	Channels Behavior	Reset and Threshold (Typical)
CH2 LVBuck2	UVP	$V_{OUT_LV2} \leq V_{OUT_LV2} \times 95\%$	50 μ s	If 0x0F[3] = 0, keep all channels in operation	If 0x0F[3] = 0, refer to Table 3 . (Alarm state)
				If 0x0F[3] = 1, disable all channels and latch off	If 0x0F[3] = 1, refer to Table 3 . (Fail-Safe state)
	OVP	$V_{OUT_LV2} \geq V_{OUT_LV2} \times 105\%$	50 μ s	If 0x10[3] = 0, keep all channels in operation	If 0x10[3] = 0, refer to Table 3 . (Alarm state)
				If 0x10[3] = 1, disable All channels and latch off	If 0x10[3] = 1, refer to Table 3 . (Fail-Safe state)
	OCP	$I_{L2_peak} \geq 2.5A$	1ms	Cycle-by-cycle detection If the condition persists for 1ms, all channels will be disabled, and the device will latch off	Refer to Table 3 . (Fail-Safe state)
Input OVP	$V_{IN_LV2} \geq 5.8V$	5 μ s	Disable all channels	$V_{IN_LV2} \leq 5.22V$, Auto-recovery	
CH3 LVBuck3	UVP	$V_{OUT_LV3} \leq V_{OUT_LV3} \times 95\%$	50 μ s	If 0x0F[2] = 0, keep all channels in operation	If 0x0F[2] = 0, refer to Table 3 . (Alarm state)
				If 0x0F[2] = 1, disable all channels and latch off	If 0x0F[2] = 1, refer to Table 3 . (Fail-Safe state)
	OVP	$V_{OUT_LV3} \geq V_{OUT_LV3} \times 105\%$	50 μ s	If 0x10[2] = 0, keep all channels in operation	If 0x10[2] = 0, refer to Table 3 . (Alarm state)
				If 0x10[2] = 1, disable all channels and latch off	If 0x10[2] = 1, refer to Table 3 . (Fail-Safe state)
	OCP	$I_{L3_peak} \geq 2.5A$	1ms	Cycle-by-cycle detection If the condition persists for 1ms, all channels will be disabled, and the device will latch off	Refer to Table 3 . (Fail-Safe state)
Input OVP	$V_{IN_LV3} \geq 5.8V$	5 μ s	Disable all channels	$V_{IN_LV3} \leq 5.22V$, Auto-recovery	

Channel	Type	Threshold (Typical)	Deglitch Time (Typical)	Channels Behavior	Reset and Threshold (Typical)
CH4 LDO1	UVP	$V_{OUT_LDO1} \leq V_{OUT_LDO1} \times 95\%$	50 μ s	If 0x0F[1] = 0, keep all channels in operation	If 0x0F[1] = 0, refer to Table 3 . (Alarm state)
				If 0x0F[1] = 1, disable all channels and latch off	If 0x0F[1] = 1, refer to Table 3 . (Fail-Safe state)
	OVP	$V_{OUT_LDO1} \geq V_{OUT_LDO1} \times 105\%$	50 μ s	If 0x10[1] = 0, keep all channels in operation	If 0x10[1] = 0, refer to Table 3 . (Alarm state)
				If 0x10[1] = 1, disable all channels and latch off	If 0x10[1] = 1, refer to Table 3 . (Fail-Safe state)
	OCP	$I_{OUT_LDO1} \geq 450\text{mA}$	1ms	Disable all channels and latch-off	Refer to Table 3 . (Fail-Safe State)
Input OVP	$V_{IN_LDO1} \geq 5.8\text{V}$	5 μ s	Disable all channels	$V_{IN_LDO1} \leq 5.3\text{V}$, Auto-recovery	
CH5 LDO2	UVP	$V_{OUT_LDO2} \leq V_{OUT_LDO2} \times 95\%$	50 μ s	If 0x0F[0] = 0, keep all channels in operation	If 0x0F[0] = 0, refer to Table 3 . (Alarm state)
				If 0x0F[0] = 1, disable all channels and latch off	If 0x0F[0] = 1, refer to Table 3 . (Fail-Safe state)
	OVP	$V_{OUT_LDO2} \geq V_{OUT_LDO2} \times 105\%$	50 μ s	If 0x10[0] = 0, keep all channels in operation	If 0x10[0] = 0, refer to Table 3 . (Alarm state)
				If 0x10[0] = 1, disable all channels and latch off	If 0x10[0] = 1, refer to Table 3 . (Fail-Safe state)
	OCP	$I_{OUT_LDO2} \geq 600\text{mA}$	1ms	Disable all channels and latch off	Refer to Table 3 . (Fail-Safe state)
Input OVP	$V_{IN_LDO2} \geq 5.8\text{V}$	5 μ s	Disable all channels	$V_{IN_LDO2} \leq 5.3\text{V}$, Auto-recovery	

Table 6. Fault Status and Event Log

Channel	Type	PGOOD	ERROUT	Event	
Base	BIST	L	L	BIST_FAULT_EVT (0x11[6] = 1)	
	OTP CRC	L	L	OTP_CRC_EVT (0x11[5] = 1)	
System	UVLO	L	L	NA	
	OVP	L	L	VIN_OV_EVT (0x11[2] = 1)	
	OTW	H	L	TWARN_EVT (0x11[4] = 1)	
	TSD	L	L	TSD_EVT (0x11[3] = 1)	
	WDT Fault	L (0xAD[1] = 1)	L		WDT_FAULT_EVT (0x12[7] = 1), WDTERR keeps H, but it follows the pull-up voltage state
		H (0xAD[1] = 0)	L		WDT_FAULT_EVT (0x12[7] = 1), WDTERR goes low for 200µs duration time, then it goes back to H state
	ERROUT	H	H	ERROUT_ALARM_EVT (0x12[6] = 1)	
I ² C CRC	H	H	NA		
CH1 HVBuck1	UVP	H (0x0F[4] = 0)	L	HVBUCK1_UV_EVT (0x13[4] = 1)	
		L (0x0F[4] = 1)			
	OVP	H (0x10[4] = 0)	L	HVBUCK1_OV_EVT (0x14[4] = 1)	
		L (0x10[4] = 1)			
	OCP	L	L	HVBUCK1_OC_EVT (0x15[4] = 1)	
	CH2 LVBuck2	UVP	H (0x0F[3] = 0)	L	LVBUCK2_UV_EVT (0x13[3] = 1)
L (0x0F[3] = 1)					
OVP		H (0x10[3] = 0)	L	LVBUCK2_OV_EVT (0x14[3] = 1)	
		L (0x10[3] = 1)			
OCP		L	L	LVBUCK2_OC_EVT (0x15[3] = 1)	
Input OVP		L	L	PVD23_OV_EVT (0x11[1] = 1)	

Channel	Type	PGOOD	ERROUT	Event
CH3 LVBuck3	UVP	H (0x0F[2] = 0)	L	LVBUCK3_UV_EVT (0x13[2] = 1)
		L (0x0F[2] = 1)		
	OVP	H (0x10[2] = 0)	L	LVBUCK3_OV_EVT (0x14[2] = 1)
		L (0x10[2] = 1)		
OCP	L	L	LVBUCK3_OC_EVT (0x15[2] = 1)	
Input OVP	L	L	PVD23_OV_EVT (0x11[1] = 1)	
CH4 LDO1	UVP	H (0x0F[1] = 0)	L	LDO1_UV_EVT (0x13[1] = 1)
		L (0x0F[1] = 1)		
	OVP	H (0x10[1] = 0)	L	LDO1_OV_EVT (0x14[1] = 1)
		L (0x10[1] = 1)		
OCP	L	L	LDO1_OC_EVT (0x15[1] = 1)	
Input OVP	L	L	PVD45_OV_EVT (0x11[0] = 1)	
CH5 LDO2	UVP	H (0x0F[0] = 0)	L	LDO2_UV_EVT (0x13[0] = 1)
		L (0x0F[0] = 1)		
	OVP	H (0x10[0] = 0)	L	LDO2_OV_EVT (0x14[0] = 1)
		L (0x10[0] = 1)		
OCP	L	L	LDO2_OC_EVT (0x15[0] = 1)	
Input OVP	L	L	PVD45_OV_EVT (0x11[0] = 1)	

18.10 Inductor Selection

18.10.1 HVBuck1, LVBuck2 and LVBuck3

Referring to the equations below, the maximum inductor current can be calculated for different load applications. The inductor saturation current should be rated higher than the calculated value. To achieve good performance and efficiency in the application, it is suggested to select an inductor with low DCR. The recommended nominal inductance is 1.5µH for HVBuck1 and 1µH for LVBuck2/LVBuck3.

$$\Delta I_L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times f_{SW} \times L}$$

$$I_{L_peak} = I_{OUT} + \frac{1}{2} \times \Delta I_L$$

where ΔI_L is the change in current through the output inductor.

18.11 Input and Output Capacitor Selection

18.11.1 HVBuck1, LVBuck2, and LVBuck3

It is recommended to use at least a 4.7μF input capacitor and a 10μF output capacitor for step-down converters. The ripple voltage is an important index for choosing output capacitor. This portion consists of two parts. One is the product of the ripple current and the ESR of the output capacitor, while the other part is formed by the charging and discharging process of the output capacitor. The output ripple can be calculated as follows.

$$\Delta V_{\text{OUTRipple}} = \Delta V_{\text{ESR}} + \Delta V_{\text{OUT}} = \Delta V_{\text{ESR}} + \frac{\Delta I_L}{8 \times C_{\text{OUT}} \times f_{\text{SW}}}$$

where $\Delta V_{\text{ESR}} = I_{\text{C_rms}} \times R_{\text{C_ESR}}$

When utilizing HVBuck1 as a standalone output in applications with an input voltage above 16V, it is recommended to add an output capacitor with a value exceeding 6.8μF to ensure optimal performance.

18.11.2 LDO1 and LDO2

Like any low dropout regulator, the external capacitor for the RTQ2081-QF must be selected carefully for regulator stability and performance. Using a 2.2μF capacitor for the LDO’s input and output is suitable. Additional capacitors paralleled on the output may provide better noise suppression but could lead to higher input inrush current when LDO outputs. This should be considered carefully.

18.12 Thermal Considerations

The junction temperature should never exceed the absolute maximum junction temperature $T_{\text{J(MAX)}}$, listed under Absolute Maximum Ratings, to avoid permanent damage to the device. The maximum allowable power dissipation depends on the thermal resistance of the IC package, the PCB layout, the rate of surrounding airflow, and the difference between the junction and ambient temperatures. The maximum power dissipation can be calculated using the following formula:

$$P_{\text{D(MAX)}} = (T_{\text{J(MAX)}} - T_{\text{A}}) / \theta_{\text{JA}}$$

where $T_{\text{J(MAX)}}$ is the maximum junction temperature, T_{A} is the ambient temperature, and θ_{JA} is the junction-to-ambient thermal resistance.

For continuous operation, the maximum operating junction temperature indicated under Recommended Operating Conditions is 125°C. The junction-to-ambient thermal resistance, θ_{JA} , is highly package dependent. For WET-WQFN-24AL 4x4 package, the thermal resistance, θ_{JA} , is 37°C/W on a standard JEDEC 51-7 high effective-thermal-conductivity four-layer test board. The maximum power dissipation at $T_{\text{A}} = 25^\circ\text{C}$ can be calculated by the following formula:

$$P_{\text{D(MAX)}} = (125^\circ\text{C} - 25^\circ\text{C}) / (37^\circ\text{C/W}) = 2.7\text{W for a WET-WQFN-24AL 4x4 package.}$$

The maximum power dissipation depends on the operating ambient temperature for the fixed $T_{\text{J(MAX)}}$ and the thermal resistance, θ_{JA} . The derating curve in [Figure 16](#) allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

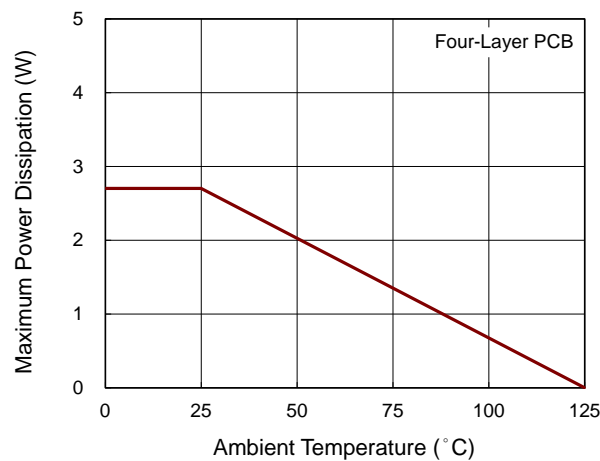


Figure 16. Derating Curve of Maximum Power Dissipation

18.13 Layout Considerations

Optimizing the PCB layout is essential for sustaining the RTQ2081-QF's superior performance. Special attention is required for the routing of high current paths and the management of fast switching nodes to maintain the IC's performance. A poor layout can lead to a host of challenges, such as degraded regulation, voltage shifts, instability, poor EMI characteristics, and diminished efficiency.

To maximize the RTQ2081-QF's performance, adhere to the following PCB layout guidelines:

- Keep the trace from the switching node to the inductor as short as possible to decrease the switching loop size.
- Locate the input and output capacitors very close to their respective pins for improved filtering effectiveness.
- Ensure that the main power traces are wide and short, optimizing their ability to carry current efficiently.
- Connect the step-down converter's output capacitor directly to the feedback network to mitigate voltage fluctuations due to the PCB trace's parasitic capacitance and inductance.
- Ensure a solid connection between AGND and PGND to a substantial ground plane, which will assist in effective thermal cooling.

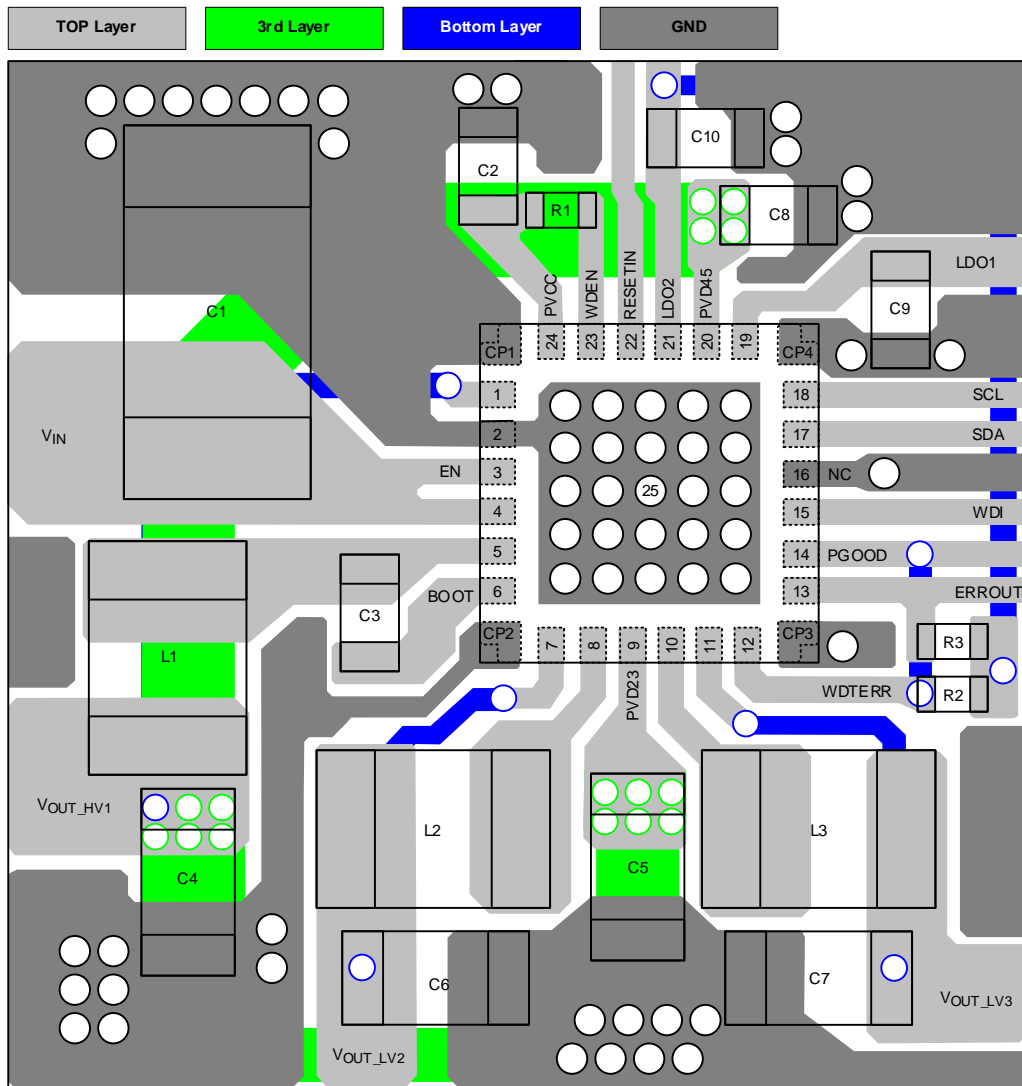


Figure 17. PCB Layout Guide

Note 9. The information provided in this section is for reference only. The customer is solely responsible for designing, validating, and testing any applications incorporating Richtek's product(s). The customer is also responsible for applicable standards and any safety, security, or other requirements.

19 Functional Register Description

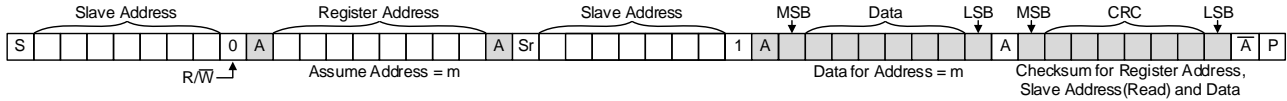
19.1 I²C Interface

19.1.1 Slave Address

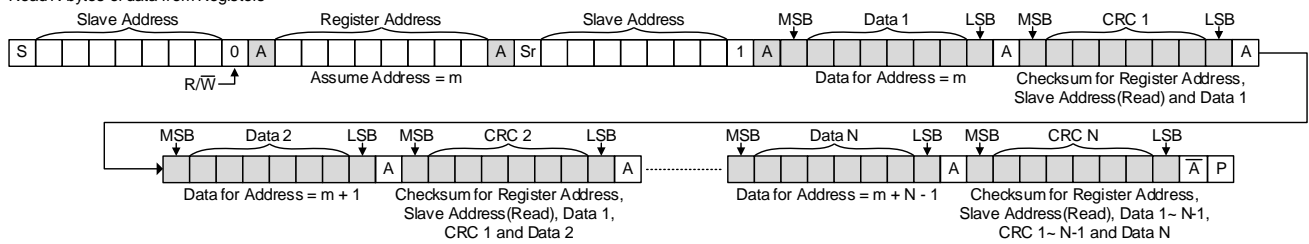
Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0 = LSB
1	1	1	0	1	0	1	R/W

19.1.2 Read and Write Function

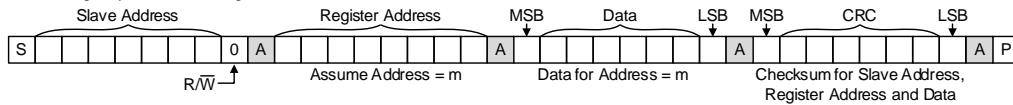
Read a single byte of data from Register



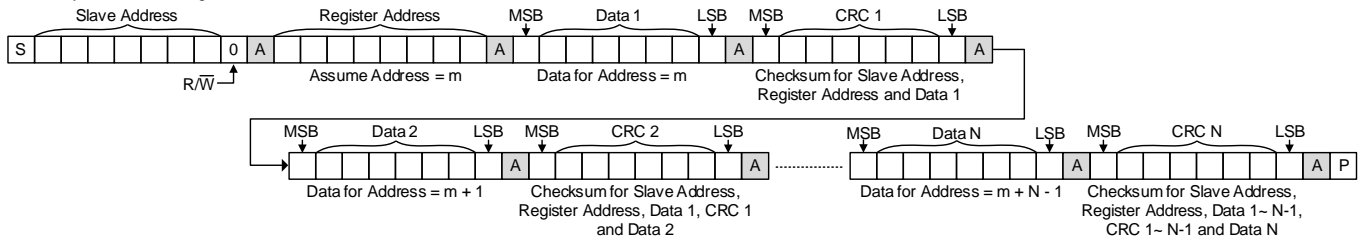
Read N bytes of data from Registers



Write a single byte of data to Register

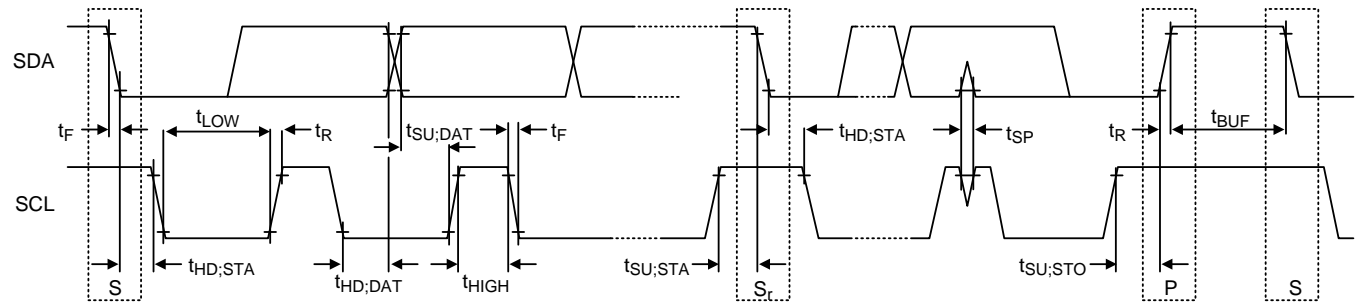


Write N bytes of data to Registers



Driven by Master, Driven by Slave, Stop, Start, Repeat Start

19.1.3 I²C Waveform Information



19.2 I²C Register Table

R: Read Only

R/W: Read and Write

W1C: Write Clear (Write '1' then it automatic clears to '0' after procedure finishes.)

Table 7.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TOP_CFG	0x00	Meaning	Reserved	Reserved	Reserved	UVLO		UVLO_DEG	REBOOT_ACT	SEQ_CTRL
		Default	0	0	0	1	0	0	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
UVLO (CFG_LOCK)			VIN UVLO (Falling/Rising) voltage setting 00: 3.3V/3.8V 01: 3.8V/4.5V 10: 4.3V/5.0V (default) 11: 6.8V/7.3V							
UVLO_DEG (CFG_LOCK)			UVLO falling deglitch time setting 0: 32μs (default) 1: 64μs							
REBOOT_ACT (CFG_LOCK)			IC auto-reboot behavior selection when the PMIC is in latch-off 0: Auto-reboot is disabled (default) 1: Auto-reboot is enabled (register keep)							
SEQ_CTRL			Sequence ON and OFF control 0: Sequence OFF 1: Sequence ON (default)							

Table 8.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_CFG	0x01	Meaning	PGOOD_DLY		BUCK_MODE	HVBUCK1_DIS	LVBUCK2_DIS	LVBUCK3_DIS	LDO1_DIS	LDO2_DIS
		Default	0	1	1	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
PGOOD_DLY (CFG_LOCK)			Time interval from the last channel soft-start completion to the PGOOD announcement							
			00: 4.7ms 01: 9.4ms (default) 10: 14.1ms 11: 18.8ms							
BUCK_MODE (CFG_LOCK)			LVBuck2 and LVBuck3 operation mode							
			0: PSM 1: FPWM (default)							
HVBUCK1_DIS (CFG_LOCK)			HVBuck1 active output discharge							
			0: Enable (default) 1: Disable							
LVBUCK2_DIS (CFG_LOCK)			LVBuck2 active output discharge							
			0: Enable (default) 1: Disable							
LVBUCK3_DIS (CFG_LOCK)			LVBuck3 active output discharge							
			0: Enable (default) 1: Disable							
LDO1_DIS (CFG_LOCK)			LDO1 active output discharge							
			0: Enable (default) 1: Disable							
LDO2_DIS (CFG_LOCK)			LDO2 active output discharge							
			0: Enable (default) 1: Disable							

Table 9.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SEQ_ON_CFG	0x02	Meaning	Reserved	ON_Td		OFF_Td		POWER_ON_SEQ		
		Default	0	0	0	1	0	1	1	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
ON_Td (CFG_LOCK)			Delay time between power-on channel and its next channel							
			00: 0ms (default) 01: 0.5ms 10: 1ms 11: 2ms							
OFF_Td (CFG_LOCK)			Delay time between power-off channel and its next channel							
			00: 1ms 01: 1.5ms 10: 2ms (default) 11: 3ms							
POWER_ON_SEQ (CFG_LOCK)			Power-on sequence settings							
			000: SEQ0 001: SEQ1 010: SEQ2 011: SEQ3 100: SEQ4 101: SEQ5 110: SEQ6 (default) 111: SEQ7							

Table 10.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
HVBUC K1_OUT_CFG	0x03	Meaning	Reserved	Reserved	Reserved	Reserved	HVBUCK1_VOUT			
		Default	0	0	0	0	1	1	1	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
HVBUCK1_VOUT (CFG_LOCK)			HVBuck1 output voltage can be set from 2.7V to 4V (100mV/step), 4.5V and 5.0V.							
			0000: 2.7V 0001: 2.8V 0010: 2.9V 0011: 3.0V 0100: 3.1V 0101: 3.2V 0110: 3.3V 0111: 3.4V 1000: 3.5V 1001: 3.6V 1010: 3.7V 1011: 3.8V 1100: 3.9V 1101: 4.0V 1110: 4.5V 1111: 5.0V (default)							

Table 11.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
LVBUC K2_OU T_CFG	0x04	Meaning	Reserved	Reserved	Reserved	LVBUCK2_VOUT				
		Default	0	0	0	1	0	0	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LVBUCK2_VOUT (CFG_LOCK)			LVBuck2 output voltage can be set from 0.6V to 1.4V (50mV/step) and 1.4V to 1.9V (100mV/step).							
			00000: 0.60V 00001: 0.65V 00010: 0.70V 00011: 0.75V 00100: 0.80V 00101: 0.85V 00110: 0.90V 00111: 0.95V 01000: 1.00V 01001: 1.05V 01010: 1.10V 01011: 1.15V 01100: 1.20V 01101: 1.25V 01110: 1.30V 01111: 1.35V 10000: 1.40V 10001: 1.50V (default) 10010: 1.60V 10011: 1.70V 10100: 1.80V 10101: 1.90V 10110: 1.90V 10111: 1.90V 11000: 1.90V 11001: 1.90V 11010: 1.90V 11011: 1.90V 11100: 1.90V 11101: 1.90V 11110: 1.90V 11111: 1.90V							

Table 12.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
LVBUC K3_OU T_CFG	0x05	Meaning	Reserved	Reserved	Reserved	LVBUCK3_VOUT				
		Default	0	0	0	0	1	0	1	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LVBUCK3_VOUT (CFG_LOCK)			LVBuck3 output voltage can be set from 0.6V to 1.4V (50mV/step) and 1.4V to 1.9V (100mV/step).							
			00000: 0.60V 00001: 0.65V 00010: 0.70V 00011: 0.75V 00100: 0.80V 00101: 0.85V 00110: 0.90V 00111: 0.95V 01000: 1.00V 01001: 1.05V 01010: 1.10V (default) 01011: 1.15V 01100: 1.20V 01101: 1.25V 01110: 1.30V 01111: 1.35V 10000: 1.40V 10001: 1.50V 10010: 1.60V 10011: 1.70V 10100: 1.80V 10101: 1.90V 10110: 1.90V 10111: 1.90V 11000: 1.90V 11001: 1.90V 11010: 1.90V 11011: 1.90V 11100: 1.90V 11101: 1.90V 11110: 1.90V 11111: 1.90V							

Table 13.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
LDO1_OUT_CFG	0x06	Meaning	Reserved	LDO1_IOUT_OC_SS		LDO1_VOUT				
		Default	0	1	1	1	0	0	1	1
		Read/Write	R/W	R	R	R/W	R/W	R/W	R/W	R/W
LDO1_IOUT_OC_SS			LDO1 output current limit at soft-start duration 00: 450mA 01: 450mA 10: 50mA 11: 150mA (default)							
LDO1_VOUT (CFG_LOCK)			LDO1 output voltage can be set from 1.8V to 1.9V (50mV/step) and 2.5V to 3.5V (50mV/step). 00000: 1.80V 00001: 1.85V 00010: 1.90V 00011: 2.50V 00100: 2.55V 00101: 2.60V 00110: 2.65V 00111: 2.70V 01000: 2.75V 01001: 2.80V 01010: 2.85V 01011: 2.90V 01100: 2.95V 01101: 3.00V 01110: 3.05V 01111: 3.10V 10000: 3.15V 10001: 3.20V 10010: 3.25V 10011: 3.30V (default) 10100: 3.35V 10101: 3.40V 10110: 3.45V 10111: 3.50V							

Table 14.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
LDO2_OUT_CFG	0x07	Meaning	Reserved	Reserved	Reserved	Reserved	LDO2_VOUT			
		Default	0	0	0	1	1	1	1	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LDO2_VOUT (CFG_LOCK)			LDO2 output voltage can be set from 1.8V to 3.3V(100mV/step).							
			0000: 1.8V 0001: 1.9V 0010: 2.0V 0011: 2.1V 0100: 2.2V 0101: 2.3V 0110: 2.4V 0111: 2.5V 1000: 2.6V 1001: 2.7V 1010: 2.8V 1011: 2.9V 1100: 3.0V 1101: 3.1V 1110: 3.2V 1111: 3.3V (default)							

Table 15.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_UVP1_CFG	0x08	Meaning	HVBUCK1_UV		LVBUCK2_UV		LVBUCK3_UV		LDO1_UV	
		Default	1	1	0	1	0	1	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
HVBUCK1_UV (CFG_LOCK)			HVBUck1 UV detection threshold with respect to target voltage 00: 95% 01: 90% 10: 85% 11: 80% (default)							
LVBUCK2_UV (CFG_LOCK)			LVBUck2 UV detection threshold with respect to target voltage 00: 96.5% 01: 95% (default) 10: 94% 11: 90%							
LVBUCK3_UV (CFG_LOCK)			LVBUck3 UV detection threshold with respect to target voltage 00: 96.5% 01: 95% (default) 10: 94% 11: 90%							
LDO1_UV (CFG_LOCK)			LDO1 UV detection threshold with respect to target voltage 00: 96.5% 01: 95% (default) 10: 94% 11: 90%							

Table 16.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_UVP2_CFG	0x09	Meaning	Reserved	Reserved	LDO2_UV		HVBUCK1_UV_DEG		LVCH_UV_DEG	
		Default	0	0	0	1	0	1	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LDO2_UV (CFG_LOCK)			LDO2 UV detection threshold with respect to target voltage							
			00: 96.5% 01: 95% (default) 10: 94% 11: 90%							
HVBUCK1_UV_DEG (CFG_LOCK)			HVBUck1 UV detection deglitch time selection							
			00: Reserved 01: 50µs (default) 10: 75µs 11: 100µs							
LVCH_UV_DEG (CFG_LOCK)			LVBUck2, LVBUck3, LDO1and LDO2 UV detection deglitch time selection							
			00: Reserved 01: 50µs (default) 10: 75µs 11: 100µs							

Table 17.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_OVP1_CFG	0x0A	Meaning	HVBUCK1_OV		LVBUCK2_OV		LVBUCK3_OV		LDO1_OV	
		Default	0	1	0	1	0	1	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
HVBUCK1_OV (CFG_LOCK)			HVBUck1 OV detection threshold with respect to target voltage							
			00: 105% 01: 110% (default) 10: 115% 11: 120%							
LVBUCK2_OV (CFG_LOCK)			LVBUck2 OV detection threshold with respect to target voltage							
			00: 103.5% 01: 105% (default) 10: 106% 11: 110%							
LVBUCK3_OV (CFG_LOCK)			LVBUck3 OV detection threshold with respect to target voltage							
			00: 103.5% 01: 105% (default) 10: 106% 11: 110%							
LDO1_OV (CFG_LOCK)			LDO1 OV detection threshold with respect to target voltage							
			00: 103.5% 01: 105% (default) 10: 106% 11: 110%							

Table 18.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_OVP2_CFG	0x0B	Meaning	Reserved	Reserved	LDO2_OV		HVBUCK1_OV_DEG		LVCH_OV_DEG	
		Default	0	0	0	1	0	1	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LDO2_OV (CFG_LOCK)			LDO2 OV detection threshold with respect to target voltage 00: 103.5% 01: 105% (default) 10: 106% 11: 110%							
HVBUCK1_OV_DEG (CFG_LOCK)			HVBUck1 OV detection deglitch time selection 00: Reserved 01: 50µs (default) 10: 75µs 11: 100µs							
LVCH_OV_DEG (CFG_LOCK)			LVBUck2, LVBUck3, LDO1 and LDO2 OV detection deglitch time selection 00: Reserved 01: 50µs (default) 10: 75µs 11: 100µs							

Table 19.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FUNC1_CFG	0x0D	Meaning	Reserved	Reserved	Reserved	RESET	RESET_ACT	FAULT_MASK	PHASE_EN	SSP_EN
		Default	0	0	0	0	0	0	1	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
RESET			SW reset and reset behavior follows 0x0D[3], RESET_ACT 0: None (default) 1: SW Reset							
RESET_ACT (CFG_LOCK)			RESET triggered registers behavior selection 0: Reset registers to default value except fault event registers (default) 1: Reset all registers to default value							
FAULT_MASK (CFG_LOCK)			All faults event mask 0: Unmask (default) 1: Mask							
PHASE_EN (CFG_LOCK)			Bucks' switching phase shift function 0: Disable 1: Enable (default)							
SSP_EN (CFG_LOCK)			Bucks' switching frequency spread spectrum function 0: Disable 1: Enable (default)							

Table 20.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
FUNC2_CFG	0x0E	Meaning	Reserved				KEEP_AWAKE	Reserved		
		Default	0	0	0	0	0	1	1	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
KEEP_AWAKE			PMIC keeps awake 0: PMIC does not keep awake (default) 1: PMIC keeps awake							

Table 21.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PROTE_C1_CFG	0x0F	Meaning	Reserved	Reserved	Reserved	HVBUCK1_UV_SD	LVBUCK2_UV_SD	LVBUCK3_UV_SD	LDO1_UV_SD	LDO2_UV_SD
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
HVBUCK1_UV_SD (CFG_LOCK)			HVBUck1 undervoltage protection behavior selection 0: Inform ECU only of fault events (default) 1: Channel latch-off and inform ECU of fault events							
LVBUCK2_UV_SD (CFG_LOCK)			LVBUck2 undervoltage protection behavior selection 0: Inform ECU only of fault events (default) 1: Channel latch-off and inform ECU of fault events							
LVBUCK3_UV_SD (CFG_LOCK)			LVBUck3 undervoltage protection behavior selection 0: Inform ECU only of fault events (default) 1: Channel latch-off and inform ECU of fault events							
LDO1_UV_SD (CFG_LOCK)			LDO1 undervoltage protection behavior selection 0: Inform ECU only of fault events (default) 1: Channel latch-off and inform ECU of fault events							
LDO2_UV_SD (CFG_LOCK)			LDO2 undervoltage protection behavior selection 0: Inform ECU only of fault events (default) 1: Channel latch-off and inform ECU of fault events							

Table 22.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
PROTE C2_ CFG	0x10	Meaning	Reserved	Reserved	Reserved	HVBUC K1_OV_ SD	LVBUCK 2_OV_ SD	LVBUCK 3_OV_ SD	LDO1_ OV_SD	LDO2_ OV_SD
		Default	0	0	0	1	1	1	1	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
HVBuck1 overvoltage protection behavior selection (CFG_LOCK)			HVBuck1 overvoltage protection behavior selection 0: Inform ECU only of fault events 1: Channel latch-off and inform ECU of fault events (default)							
LVBUCK2_OV_SD (CFG_LOCK)			LVBUCK2 overvoltage protection behavior selection 0: Inform ECU only of fault events 1: Channel latch-off and inform ECU of fault events (default)							
LVBUCK3_OV_SD (CFG_LOCK)			LVBUCK3 overvoltage protection behavior selection 0: Inform ECU only of fault events 1: Channel latch-off and inform ECU of fault events (default)							
LDO1_OV_SD (CFG_LOCK)			LDO1 overvoltage protection behavior selection 0: Inform ECU only of fault events 1: Channel latch-off and inform ECU of fault events (default)							
LDO2_OV_SD (CFG_LOCK)			LDO2 overvoltage protection behavior selection 0: Inform ECU only of fault events 1: Channel latch-off and inform ECU of fault events (default)							

Table 23.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
BASE1_EVT	0x11	Meaning	Reserved	BIST_FAULT_EVT	OTP_CRC_EVT	TWARN_EVT	TSD_EVT	VIN_OV_EVT	PVD23_OV_EVT	PVD45_OV_EVT
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	W1C	W1C	W1C	W1C	W1C	W1C	W1C
BIST_FAULT_EVT			BIST fault acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							
OTP_CRC_EVT			Internal OTP CRC checking fault acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							
TWARN_EVT			Thermal warning event acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							
TSD_EVT			Thermal shutdown event acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							
VIN_OV_EVT			VIN overvoltage threshold event acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							
PVD23_OV_EVT			PVD23 overvoltage threshold event acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							
PVD45_OV_EVT			PVD45 overvoltage threshold event acknowledgement 0: No faults detected, or faults masked (default) 1: Fault detected							

Table 24.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
BASE2_EVT	0x12	Meaning	WDT_FAULT_EVT	ERROUT_ALARM_EVT	Reserved					
		Default	0	0	0	0	0	0	0	0
		Read/Write	W1C	W1C	R/W	R/W	W1C	W1C	W1C	W1C
WDT_FAULT_EVT			WDT fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
ERROUT_ALARM_EVT			ERROUT logic fault event 0: No faults detected, or faults masked (default) 1: Fault detected							

Table 25.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_UV_EVT	0x13	Meaning	Reserved	Reserved	Reserved	HVBUC K1_UV_ EVT	LVBUCK 2_UV_ EVT	LVBUCK 3_UV_ EVT	LDO1_ UV_EVT	LDO2_ UV_EVT
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	W1C	W1C	W1C	W1C	W1C
HVBUCK1_UV_EVT			HVBUck1 undervoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LVBUCK2_UV_EVT			LVBUck2 undervoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LVBUCK3_UV_EVT			LVBUck3 undervoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LDO1_UV_EVT			LDO1 undervoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LDO2_UV_EVT			LDO2 undervoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							

Table 26.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_OV_EVT	0x14	Meaning	Reserved	Reserved	Reserved	HVBUC K1_OV_ EVT	LVBUCK 2_OV_ EVT	LVBUCK 3_OV_ EVT	LDO1_ OV_EVT	LDO2_ OV_EVT
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	W1C	W1C	W1C	W1C	W1C
HVBUCK1_OV_EVT			HVBuck1 overvoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LVBUCK2_OV_EVT			LVBUCK2 overvoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LVBUCK3_OV_EVT			LVBUCK3 overvoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LDO1_OV_EVT			LDO1 overvoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							
LDO2_OV_EVT			LDO2 overvoltage fault event 0: No faults detected, or faults masked (default) 1: Fault detected							

Table 27.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
CH_OC_EVT	0x15	Meaning	Reserved	Reserved	Reserved	HVBUC K1_OC_ EVT	LVBUCK 2_OC_ EVT	LVBUCK 3_OC_ EVT	LDO1_ OC_EVT	LDO2_ OC_EVT
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	W1C	W1C	W1C	W1C	W1C
HVBUCK1_OC_EVT		HVBUck1 overcurrent fault event 0: No faults detected, or faults masked (default) 1: Fault detected								
LVBUCK2_OC_EVT		LVBUck2 overcurrent fault event 0: No faults detected, or faults masked (default) 1: Fault detected								
LVBUCK3_OC_EVT		LVBUck3 overcurrent fault event 0: No faults detected, or faults masked (default) 1: Fault detected								
LDO1_OC_EVT		LDO1 overcurrent fault event 0: No faults detected, or faults masked (default) 1: Fault detected								
LDO2_OC_EVT		LDO2 overcurrent fault event 0: No faults detected, or faults masked (default) 1: Fault detected								

Table 28.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
DEV_STAT	0x16	Meaning	Reserved	Reserved	Reserved	Reserved	Reserved	DEV_STATE		
		Default	0	0	0	0	0	0	0	0
		Read/Write	R	R	R	R	R	R	R	R
DEV_STATE		Indicate the PMIC present state 000: Regulator-Off state or BIST state (default) 001: Standby state 010: Power-On state 011: Active state 100: Alarm state 101: Fail-Safe state								

Table 29.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP_CRC_1	0x18	Meaning	CRC_START	CRC_FAIL	CRC_DONE	CRC_EN	Reserved	Reserved	Reserved	Reserved
		Default	0	0	0	1	0	0	0	0
		Read/Write	R/W	R	R	R/W	R/W	R/W	R/W	R/W
CRC_START		For OTP CRC value calculation, the calculated value is displayed at 0x19. 0: None (default) 1: Enable								
CRC_FAIL		OTP CRC comparison result 0: None or CRC pass (default) 1: CRC fail								
CRC_DONE		OTP CRC calculation process 0: None or calculating (default) 1: Calculation completed								
CRC_EN		OTP CRC function 0: Disable 1: Enable (default)								

Table 30.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP_CRC_2	0x19	Meaning	OTP_CRC_RESULT							
		Default	0	0	0	0	0	0	0	0
		Read/Write	R	R	R	R	R	R	R	R
OTP_CRC_RESULT		OTP CRC calculation value								

Table 31.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TM_PASS_CODE1	0x20	Meaning	TM_PASS_CODE1							
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
TM_PASS_CODE1		To enter guest mode, set 0x20 = 8'h69 and 0x21 = 8'h96 sequentially. To leave guest mode, set 0x20 ≠ 8'h69 or 0x21 ≠ 8'h96.								

Table 32.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
TM_PASS_CODE2	0x21	Meaning	TM_PASS_CODE2							
		Default	0	0	0	0	0	0	0	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
TM_PASS_CODE2			To enter guest mode, set 0x20 = 8'h69 and 0x21 = 8'h96 sequentially. To leave guest mode, set 0x20 ≠ 8'h69 or 0x21 ≠ 8'h96.							

Table 33.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
WDT_CFG	0xAD	Meaning	WDT_EN	WDT_UPPER		WDT_LOWER		WDT_LOWER_EN	WDT_FAULT	WDT_KICK
		Default	0	0	0	0	0	0	0	
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
WDT_EN			Watchdog Timer enable setting 0: WDT_disable (default) 1: WDT_enable							
WDT_UPPER			WDT upper limit setting 00: 250ms (default) 01: 62ms 10: 53ms 11: 53ms							
WDT_LOWER			WDT lower limit setting 00: 139ms (default) 01: 35ms 10: 29ms 11: 29ms							
WDT_LOWER_EN			WDT lower limit function enable 0: Disable lower limit (default) 1: Enable lower limit							
WDT_FAULT			WDT fault action 0: Fault report only (default) 1: PMIC Reset							
WDT_KICK			I ² C kicking command 0: Writing 0 to not to kick the watchdog timer (default) 1: Writing 1 to kick the watchdog timer							

Table 34.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP34	0xE2	Meaning	UV_LVCH		OV_LVCH		UV_DEG_LVCH		OV_DEG_LVCH	
		Default	0	1	0	1	0	1	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
UV_LVCH			LVBuck2, LVBuck3, LDO1 and LDO2 UV detection threshold with respect to target voltage 00: 96.5% 01: 95% (default) 10: 94% 11: 90%							
OV_LVCH			LVBuck2, LVBuck3, LDO1 and LDO2 OV detection threshold with respect to target voltage 00: 103.5% 01: 105% (default) 10: 106% 11: 110%							
UV_DEG_LVCH			LVBuck2, LVBuck3, LDO1 and LDO2 UV detection deglitch time selection 00: Reserved 01: 50μs (default) 10: 75μs 11: 100μs							
OV_DEG_LVCH			LVBuck2, LVBuck3, LDO1 and LDO2 OV detection deglitch time selection 00: Reserved 01: 50μs (default) 10: 75μs 11: 100μs							

Table 35.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP35	0xE3	Meaning	OV_HVCH		UVLO		UVLO_DEG	CH_OV_SD	CH_UV_SD	REBOOT
		Default	0	1	1	0	0	1	0	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
OV_HVCH			HVBUck1 OV detection threshold with respect to target voltage 00: 105% 01: 110% (default) 10: 115% 11: 120%							
UVLO			VIN UVLO (falling/rising) voltage setting 00: 3.3V/3.8V 01: 3.8V/4.5V 10: 4.3V/5.0V (default) 11: 6.8V/7.3V							
UVLO_DEG			UVLO falling deglitch time setting 0: 32 μ s (default) 1: 64 μ s							
CH_OV_SD			HVBUck1, LVBUck2, LVBUck3, LDO1, and LDO2 overvoltage protection behavior selection 0: Inform ECU only of fault events 1: Channel latch-off and inform ECU of fault events (default)							
CH_UV_SD			HVBUck1, LVBUck2, LVBUck3, LDO1, and LDO2 undervoltage protection behavior selection 0: Inform ECU only of fault events (default) 1: Channel latch-off and inform ECU of fault events							
REBOOT			IC auto-reboot behavior selection when the PMIC is latch off 0: Auto-reboot is disabled (default) 1: Auto-reboot is enabled (register keep)							

Table 36.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP36	0xE4	Meaning	SEQ_CTRL	ON_Td		OFF_Td		POWER_ON_SEQ		
		Default	1	0	0	1	0	1	1	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
SEQ_CTRL		Sequence on and off control 0: Sequence off 1: Sequence on (default)								
ON_Td		Delay time between the power-on channel and its next channel 00: 0ms (default) 01: 0.5ms 10: 1ms 11: 2ms								
OFF_Td		Delay time between the power-off channel and its next channel 00: 1ms 01: 1.5ms 10: 2ms (default) 11: 3ms								
POWER_ON_SEQ		Power-on sequence setting 000: SEQ0 001: SEQ1 010: SEQ2 011: SEQ3 100: SEQ4 101: SEQ5 110: SEQ6 (default) 111: SEQ7								

Table 37.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP37	0xE5	Meaning	HVBUCK1_VOUT				LVBUCK2_VOUT			
		Default	1	1	1	1	1	0	1	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
HVBUCK1_VOUT			HVBUCK1 output voltage can be set from 2.7V to 4V (100mV/step), 4.5V and 5.0V 0000: 2.7V 0001: 2.8V 0010: 2.9V 0011: 3.0V 0100: 3.1V 0101: 3.2V 0110: 3.3V 0111: 3.4V 1000: 3.5V 1001: 3.6V 1010: 3.7V 1011: 3.8V 1100: 3.9V 1101: 4.0V 1110: 4.5V 1111: 5.0V (default)							
			LVBUCK2_VOUT			LVBUCK2 output voltage can be set from 0.9V to 1.4V (50mV/step) and 1.4V to 1.9V (100mV/step) 0000: 0.90V 0001: 0.95V 0010: 1.00V 0011: 1.05V 0100: 1.10V 0101: 1.15V 0110: 1.20V 0111: 1.25V 1000: 1.30V 1001: 1.35V 1010: 1.40V 1011: 1.50V (default) 1100: 1.60V 1101: 1.70V 1110: 1.80V 1111: 1.90V				

Table 38.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP38	0xE6	Meaning	LVBUCK3_VOUT				LDO1_VOUT			
		Default	0	1	0	0	1	1	0	1
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LVBUCK3_VOUT			LVBUCK3 output voltage can be set from 0.9V to 1.4V (50mV/step) and 1.4V to 1.9V (100mV/step)							
			0000: 0.90V 0001: 0.95V 0010: 1.00V 0011: 1.05V 0100: 1.10V (default) 0101: 1.15V 0110: 1.20V 0111: 1.25V 1000: 1.30V 1001: 1.35V 1010: 1.40V 1011: 1.50V 1100: 1.60V 1101: 1.70V 1110: 1.80V 1111: 1.90V							
LDO1_VOUT			LDO1 output voltage can be set from 1.8V and 2.7V to 3.4V (50mV/step)							
			0000: 1.80V 0001: 2.70V 0010: 2.75V 0011: 2.80V 0100: 2.85V 0101: 2.90V 0110: 2.95V 0111: 3.00V 1000: 3.05V 1001: 3.10V 1010: 3.15V 1011: 3.20V 1100: 3.25V 1101: 3.30V (default) 1110: 3.35V 1111: 3.40V							

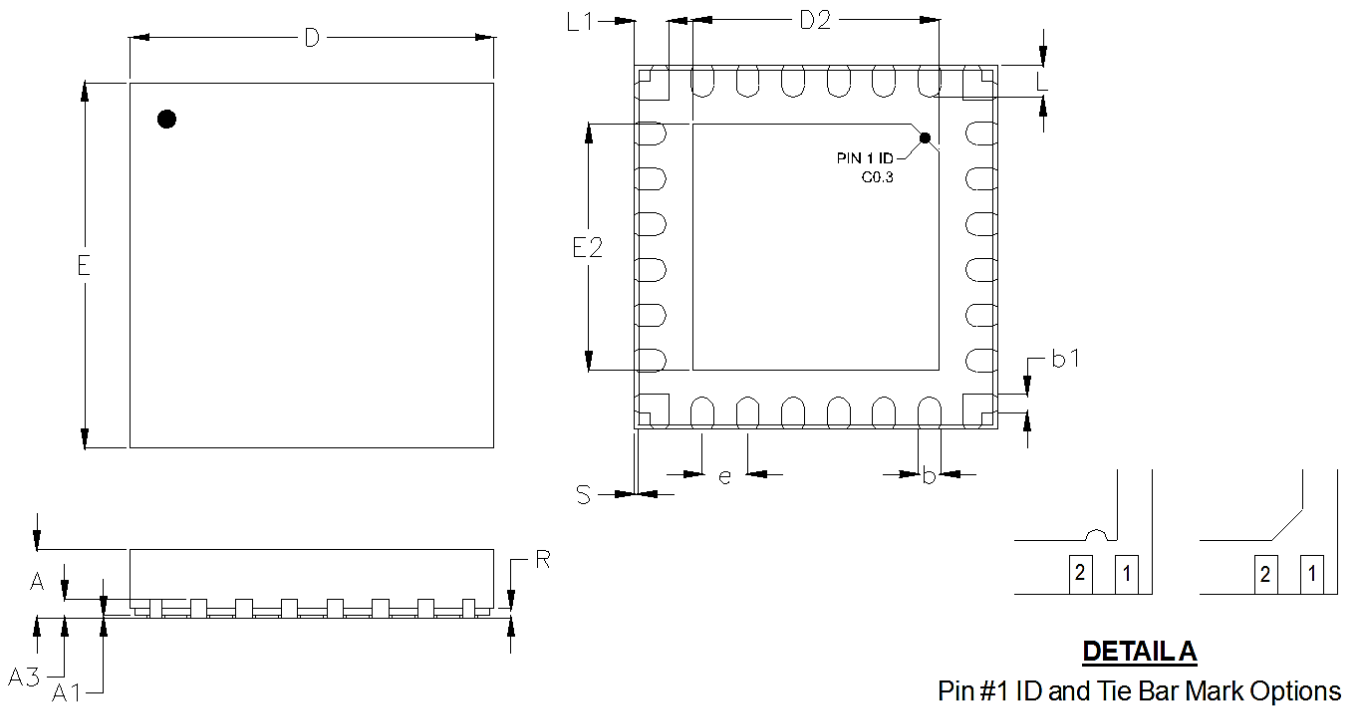
Table 39.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP39	0xE7	Meaning	LDO2_VOUT		Reserved		OTP_TRIM_DONE	Reserved		ADR
		Default	1	1	1	1	0	1	1	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
LDO2_VOUT		LDO2 output voltage can be set from 1.8V, 2.5V, 2.9V and 3.3V 00: 1.8V 01: 2.5V 10: 2.9V 11: 3.3V (default)								
OTP_TRIM_DONE		All open OTPs will be trimmed and locked 0: Non-trimmed (default) 1: All open OTPs are trimmed and locked								
ADR		PMIC slave address 0: 75h (7bit) (default) 1: 76h (7bit)								

Table 40.

Address Name	Register Address	Description	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
OTP40	0xE8	Meaning	CRC_B7	CRC_B6	CRC_B5	CRC_B4	CRC_B3	CRC_B2	CRC_B1	CRC_B0
		Default	1	0	0	1	1	0	1	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
CRC_CODE		After changing settings of OTP34 to OTP40, write the register 0x18[7] = 1 to get the new CRC shown on the register 0x19 that calculated automatically by PMIC. Fill the new CRC value into OTP40 to pass PMIC BIST.								

20 Outline Dimension

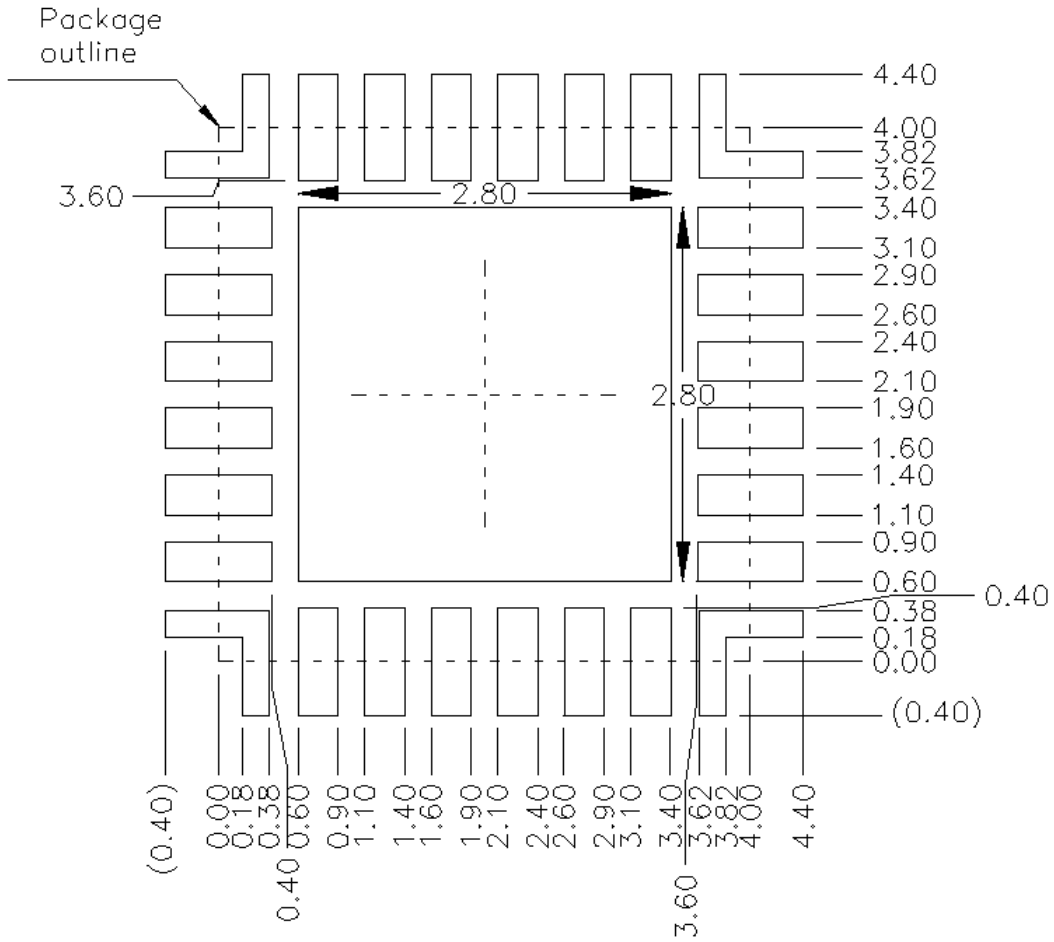


Note : The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.175	0.250	0.007	0.010
b	0.200	0.300	0.008	0.012
b1	0.150	0.250	0.006	0.010
D	3.900	4.100	0.154	0.161
D2	2.650	2.750	0.104	0.108
E	3.900	4.100	0.154	0.161
E2	2.650	2.750	0.104	0.108
e	0.500		0.020	
L	0.300	0.400	0.012	0.016
L1	0.330	0.430	0.013	0.017
R	0.050	0.150	0.002	0.006
S	0.001	0.090	0.000	0.004

WET W-Type 24AL QFN 4x4 Package

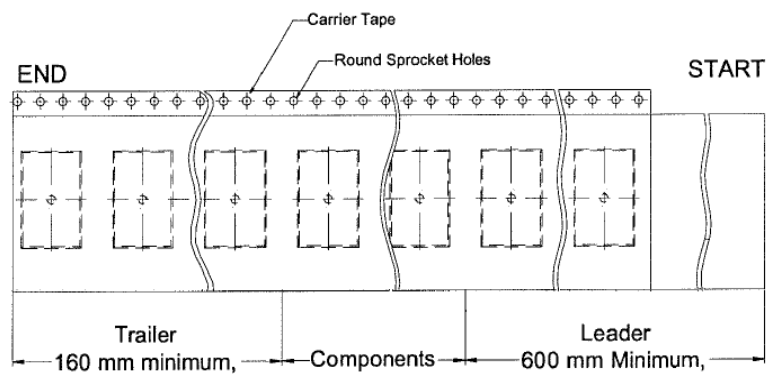
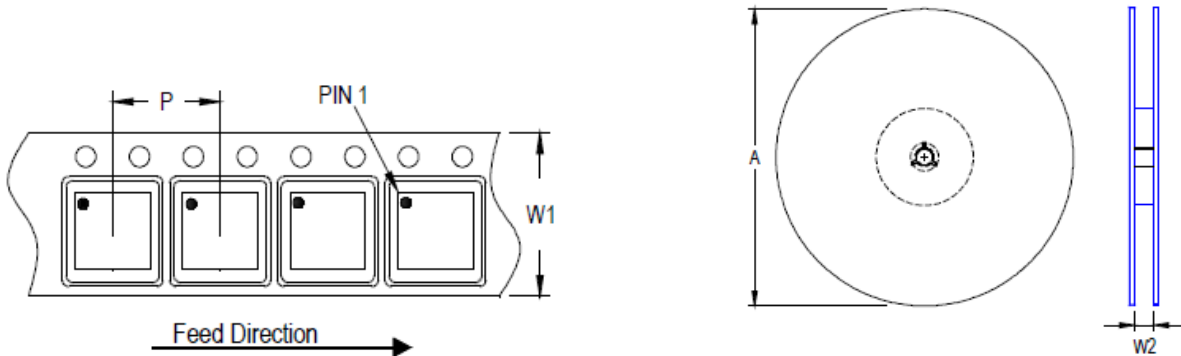
21 Footprint Information



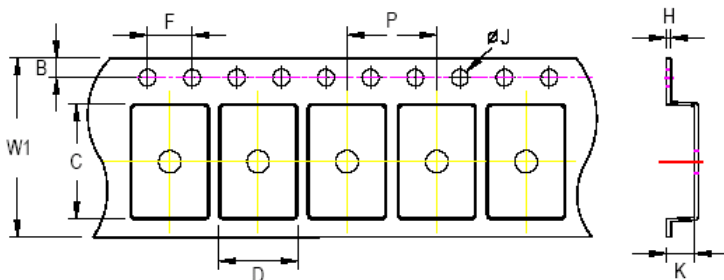
Tolerance (mm)
±0.050

22 Packing Information

22.1 Tape and Reel Data









Package Type	Tape Size (W1) (mm)	Pocket Pitch (P) (mm)	Reel Size (A)		Units per Reel	Trailer (mm)	Leader (mm)	Reel Width (W2) Min./Max. (mm)
			(mm)	(in)				
QFN/DFN 4x4	12	8	180	7	1,500	160	600	12.4/14.4



C, D, and K are determined by component size.
The clearance between the components and the cavity is as follows:
- For 12mm carrier tape: 0.5mm max.

Tape Size	W1		P		B		F		ØJ		H
	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Max.	
12mm	12.3mm	7.9mm	8.1mm	1.65mm	1.85mm	3.9mm	4.1mm	1.5mm	1.6mm	0.6mm	

22.2 Tape and Reel Packing

Step	Photo/Description	Step	Photo/Description
1	 <p>Reel 7"</p>	4	 <p>3 reels per inner box Box A</p>
2	 <p>HIC & Desiccant (1 Unit) inside</p>	5	 <p>12 inner boxes per outer box</p>
3	 <p>Caution label is on backside of Al bag</p>	6	 <p>Outer box Carton A</p>

Package	Container		Reel			Box			Carton		
	Size	Units	Item	Reels	Units	Item	Boxes	Unit			
QFN/DFN 4x4	7"	1,500	Box A	3	4,500	Carton A	12	54,000			
			Box E	1	1,500	For Combined or Partial Reel.					

22.3 Packing Material Anti-ESD Property

Surface Resistance	Aluminum Bag	Reel	Cover tape	Carrier tape	Tube	Protection Band
Ω/cm^2	10^4 to 10^{11}	10^4 to 10^{11}	10^4 to 10^{11}	10^4 to 10^{11}	10^4 to 10^{11}	10^4 to 10^{11}

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23 Datasheet Revision History

Version	Date	Description	Item
00	2024/8/19	Final	